

Spansion® NOR and NAND Flash Memory
Competitive Cross Reference Guide
April 2013



Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
	Micron	ADP	1.7-2.0V	-	128	PC28F128G18	x16	Uniform Sector/ 8 Banks	96ns/133MHz	64-Ball Easy-BGA	-30 to +85C	S29WS128P	No	No	Spansion S29WS128P has 16 banks. Contact factory for alternate solutions.
Macronix	Micron	ADP ADM	1.7-2.0V	-	256	PC28F256G18	x16	Uniform Sector/ 8 Banks	96ns/133MHz	64-Ball Easy-BGA	-30 to +85C	ADP: S29WS256P ADM: S29VS256R	No	No	Spansion S29WS256P has 16 banks. Contact factory for alternate solutions.
	Micron	ADP	1.7-2.0V	-	512	PC28F512G18	x16	Uniform Sector/ 8 Banks	96ns/133MHz	64-Ball Easy-BGA	-30 to +85C	S29WS512P	No	No	Spansion S29WS512P and S29NS512P has 16 banks. Contact factory for alternate solutions.
Samsung	Micron	ADP	1.7-2.0V	-	1G	PC28F00AG18	x16	Uniform Sector/ 8 Banks	96ns/133MHz	64-Ball Easy-BGA	-30 to +85C	S29WS-P	No	No	Contact factory for alternate solutions.
	Micron	ADP ADM	1.7-2.0V	-	128	PF48F3000MOY	x16	Uniform Sector/ 8 Banks	96ns/133MHz	88-Ball FBGA	-30 to +85C	ADP: S29WS128P ADM: S29VS128R	No	No	Spansion S29WS128P has 16 banks. Contact factory for alternate solutions.
SST	Micron	ADP	1.7-2.0V	-	256	PF48F4000MOY	x16	Uniform Sector/ 8 Banks	96ns/133MHz	107-Ball FBGA	-30 to +85C	S29WS256P	No	No	Spansion S29WS256P has 16 banks. Contact factory for alternate solutions.
	Micron	ADP ADM	1.7-2.0V	-	512	PF48F5000MOY	x16	Uniform Sector/ 8 Banks	96ns/133MHz	105-Ball FBGA	-30 to +85C	ADP: S29WS512P ADM: S29NS512P	No	No	Spansion S29WS512P and S29NS512P has 16 banks. Contact factory for alternate solutions.
Atmel	Micron	ADP ADM	1.7-2.0V	-	1G	PF48F6000MOY	x16	Uniform Sector/ 8 Banks	96ns/133MHz	105-Ball FBGA	-30 to +85C	ADP: S29WS-P ADM: S29NS-P	No	No	Contact factory for alternate solutions.
	Micron	ADP ADM	1.7-2.0V	-	256	PF48F4000LOY	x16	Boot Sector/ 16 Banks	100ns/110MHz	88-Ball MCP	-25 to +85C	ADP: S29WS256P ADM: S29VS256R	No	No	Spansion S29VS256R has 8 banks. Contact factory for alternate solutions.
	Micron	ADP ADM	1.7-2.0V	-	512	PF48F5000LOY	x16	Uniform Sector/ 16 Banks	100ns/110MHz	88-Ball MCP 105-Ball MCP	-25 to +85C	ADP: S29WS512P ADM: S29NS512P	No	No	Contact factory for alternate solutions.
EON	Micron	ADP	1.7-2.0V	1.7-2.0V	512	M58PR512LE	x16	Uniform Sector/ 8 Banks	96ns/108MHz	105-Ball FBGA 107-Ball FBGA	-30 to +85C	S29WS512P	No	No	Contact factory for alternate solutions.
	Micron	ADP	1.7-2.0V	1.7-2.0V	1G	M58PR001LE	x16	Uniform Sector/ 8 Banks	96ns/108MHz	105-Ball FBGA 107-Ball FBGA	-30 to +85C	S29WS-P	No	No	Contact factory for alternate solutions.
AMIC	Micron	ADM	1.7-2.0V	1.7-2.0V	128	M58LR128KC M58LR128KD	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-30 to +85C	S29VS128R	Yes	No	Spansion S29VS128R offers faster burst speed.
	Micron	ADP	1.7-2.0V	1.7-2.0V	128	M58LR128KT M58LR128KB	x16	Boot Sector/ 16 Banks	70ns/66MHz	56-Ball FBGA	-30 to +85C	S29WS128P	No	No	Contact factory for alternate solutions.
Winbond	Micron	ADM	1.7-2.0V	1.7-2.0V	256	M58LR256KC M58LR256KD	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-30 to +85C	S29VS256R	Yes	No	Spansion S29VS256R offers faster burst speed.
	Micron	ADP	1.7-2.0V	1.7-2.0V	256	M58LR256KT M58LR256KB	x16	Boot Sector/ 16 Banks	70ns/66MHz	79-Ball FBGA 88-Ball FBGA	-30 to +85C	S29WS256P	No	No	Contact factory for alternate solutions.
ESMT	Micron	ADP	1.7-2.0V	2.7-3.6V	128	M58LT128	x16	Boot Sector/ 16 Banks	85ns/52MHz	64-Ball TBGA	-40 to +85C	S29WS128P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	2.7-3.6V	256	M58LT256	x16	Boot Sector/ 16 Banks	85ns/52MHz	64-Ball TBGA	-40 to +85C	S29WS256P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
ESI, Chingis, GigaDevice	Micron	ADM	1.7-2.0V	1.7-2.0V	16	M58WR016KU M58WR016KL	x16	Boot Sector/ 4 Banks	70ns/66MHz	44-Ball FBGA	-40 to +85C	S29AS016J	No	No	S29AS016J is a standard NOR device.
	Micron	ADP	1.7-2.0V	1.7-2.0V	16	M58WR016KT M58WR016KB	x16	Boot Sector/ 4 Banks	70ns/66MHz	56-Ball FBGA 88-Ball FBGA	-40 to +85C	S29AS016J	No	No	S29AS016J is a standard NOR device.
Micron, SST, EON, MCP	Micron	ADM	1.7-2.0V	1.7-2.0V	32	M58WR032KU M58WR032KL	x16	Boot Sector/ 8 Banks	70ns/66MHz	44-Ball FBGA	-40 to +85C	S29VS064R	Yes	No	Spansion S29VS064R is pin-compatible with 44-Ball FBGA.
	Micron	ADP	1.7-2.0V	1.7-2.0V	32	M58WR032KT M58WR032KB	x16	Boot Sector/ 8 Banks	70ns/66MHz	56-Ball FBGA 88-Ball FBGA	-40 to +85C	S29VS064R	No	No	Contact factory for alternate solutions.
NAND	Micron	ADM	1.7-2.0V	1.7-2.0V	64	M58WR064KU M58WR064KL	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-40 to +85C	S29VS064R	Yes	No	Spansion S29VS064R is pin-compatible with 44-Ball FBGA.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
	Micron	ADP	1.7-2.0V	1.7-2.0V	64	M58WR064KT M58WR064KB	x16	Boot Sector/ 16 Banks	70ns/66MHz	56-Ball FBGA 88-Ball FBGA	-40 to +85C	S29WS064R	No	No	Contact factory for alternate solutions.
Macronix	Micron	ADP	1.7-2.0V	2.7-3.3V	32	M58WT032	x16	Boot Sector/ 8 Banks	70ns/52MHz	88-Ball FBGA	-40 to +85C	S29WS064R	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	2.7-3.3V	64	M58WT064	x16	Boot Sector/ 16 Banks	70ns/52MHz	88-Ball FBGA	-40 to +85C	S29WS064R	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
Samsung	Micron	ADP	1.7-2.0V	1.7-3.6V	64	JS28F640P30 PC28F640P30 RC28F640P30	x16	Boot Sector	65ns (BGA) 75ns (TSOP)/52MHz	64-Ball Easy-BGA 56-Pin TSOP	-40 to +85C	S29WS064R	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	1.7-3.6V	128	JS28F128P30 PC28F128P30 RC28F128P30	x16	Boot Sector	65ns (BGA) 75ns (TSOP)/52MHz	64-Ball Easy-BGA 56-Pin TSOP	-40 to +85C	S29WS128P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
SST	Micron	ADP	1.7-2.0V	1.7-3.6V	256	JS28F256P30 PC28F256P30 RC28F256P30	x16	Boot Sector	100ns (BGA) 110ns (TSOP)/52MHz	64-Ball Easy-BGA 56-Pin TSOP	-40 to +85C	S29WS256P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
Atmel	Micron	ADP	1.7-2.0V	1.7-3.6V	512	JS28F512P30 PC28F512P30	x16	Uniform/ Boot Sector	100ns (BGA) 110ns (TSOP)/52MHz	64-Ball Easy-BGA 56-Pin TSOP	-40 to +85C	S29WS512P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	1.7-3.6V	1G	JS28F00AP30 PC28F00AP30 RC28F00AP30	x16	Uniform/ Boot Sector	100ns (BGA) 105ns (TSOP)/52MHz	64-Ball Easy-BGA 56-Pin TSOP	-40 to +85C	S29GL01GS	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
EON	Micron	ADP	1.7-2.0V	1.7-3.6V	2G	PC28F00BP30	x16	Uniform	100ns/52MHz	64-Ball Easy-BGA	-40 to +85C	S70GL02GS	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	1.7-3.6V	64	PF48F2000POZ RD48F2000POZ	x16	Boot Sector	85ns/52MHz	88-Ball SCSP	-40 to +85C	S29WS064R	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
AMIC	Micron	ADP	1.7-2.0V	1.7-3.6V	128	PF48F3000POZ RD48F3000POZ	x16	Boot Sector	85ns/52MHz	88-Ball SCSP	-40 to +85C	S29WS128P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	1.7-2.0V	1.7-3.6V	256	PF48F4000POZ RD48F4000POZ	x16	Boot Sector	85ns/52MHz	88-Ball SCSP	-40 to +85C	S29WS256P	No	No	Spansion does not offer 3V VIO for 1.8V VCC devices.
Winbond	Micron	ADP	1.7-2.0V	1.7-3.6V	512	PC48F4400POV PF48F4400POV RC48F4400POV RD48F4400POV	x16	Boot Sector	100ns/52MHz	64-Ball Easy-BGA 88-Ball SCSP	-40 to +85C	S29WS512P	No	No	This Numonyx device is a dual-die stack. Spansion does not offer 3V VIO for 1.8V VCC devices.
	Micron	ADP	2.7-3.6	2.7-3.6	8	M29W800D	x8, x16	Boot Sector	45, 70, 90ns	48-Pin TSOP 48-Ball TFBGA 44-Pin SOP	-40 to +85C	S29AL008J	Yes	Yes	Numonyx device does not have WP#.
ESMT	Micron	ADP	2.7-3.6	2.7-3.6	8	M29W800F	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +125C	S29AL008J	Yes	Yes	Numonyx device does not have WP#.
	Micron	ADP	2.7-3.6	2.7-3.6	16	M29W160E	x8, x16	Boot Sector	70, 80, 90ns	48-Pin TSOP 48-Ball TFBGA 64-Ball FBGA	-40 to +85C	S29AL016J	Yes	Yes	S29AL016J is pin compatible with 48-Pin TSOP and 48-Ball TFBGA. Numonyx device does not have WP#.
ESI, Chingis, GigaDevice	Micron	ADP	2.5-3.6	2.5-3.6	16	M29W160F	x8, x16	Boot Sector	70, 80ns	48-Pin TSOP 48-Ball TFBGA	-40 to +125C	S29AL016J	Yes	Yes	Numonyx device does not have WP#.
Micron, SST, EON, MCP	Micron	ADP	2.7-3.6	2.7-3.6	32	M29W320D	x8, x16	Boot Sector	70, 80, 90ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C -40 to +125C	S29GL032N	Yes	Yes	Different boot sector architecture.
	Micron	ADP	2.7-3.6	2.7-3.6	32	M29W320E	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	-
NAND	Micron	ADP	2.5-3.6	2.5-3.6	32	M29W320F	x8, x16	Boot Sector	70, 80ns	48-Pin TSOP 48-Ball TFBGA	-40 to +125C	S29GL032N	Yes	Yes	Different boot sector architecture.

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Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
	Micron	ADP	2.7-3.6	2.7-3.6	64	M29W640F	x8, x16	Boot Sector	60, 70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29GL064N	Yes	Yes	S29GL064N has larger page-read size.
Macronix	Micron	ADP	2.7-3.6	2.7-3.6	64	M29W640G	x8, x16	Uniform/ Boot Sector	60, 70, 90ns	48-Pin TSOP 48-Ball TFBGA 56-Pin TSOP 64-Ball FBGA	-40 to +85C -40 to +125C	S29GL064N	Yes	Yes	S29GL064N has larger page-read size. S29GL064N supports VIO of 1.65 to 3.6 on uniform sector models. Refer to datasheet for best match package and sector architecture model.
Samsung	Micron	ADP	2.7-3.6	2.7-3.6	64	M29W064F	x8, x16	Boot Sector	60, 70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C -40 to +125C	S29GL064N	Yes	Yes	S29GL064N has larger page-read size.
	Micron	ADP	2.7-3.6	2.7-3.6	128	M29W128F	x8, x16	Uniform Sector	60ns	56-Pin TSOP 64-Ball TBGA	-40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16. Different sector sizes.
SST	Micron	ADP	2.7-3.6	1.65-3.6	128	M29W128G	x8, x16	Uniform Sector	60, 70, 80ns	56-Pin TSOP 64-Ball TBGA 64-Ball FBGA	0 to +70C -40 to +85C -40 to +125C	S29GL128S S29GL128P	Yes	Yes	Numonyx device access time is 80ns if full VIO is needed. S29GL128S supports x16-only. S29GL128P supports x8/x16.
Atmel	Micron	ADP	2.7-3.6	1.65-3.6	256	M29W256G	x8, x16	Uniform Sector	60, 70, 80ns	56-Pin TSOP 64-Ball TBGA 64-Ball FBGA	0 to +70C -40 to +85C	S29GL256S S29GL256P	Yes	Yes	Numonyx device access time is 80ns if full VIO is needed. S29GL256S supports x16-only. S29GL256P supports x8/x16.
	Micron	ADP	2.7-3.6	2.7-3.6	32	M29DW323D	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29JL032J S29PL032J	Yes	Yes	Bank architecture is similar to S29JL032J model 31 or 32. S29JL032J is not a page-mode device; S29PL032J is available as 48-ball FBGA only.
EON	Micron	ADP	2.7-3.6	2.7-3.6	32	M29DW324D	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29JL032J S29PL032J	Yes	Yes	Bank architecture is similar to S29JL032J model 41 or 42. S29JL032J is not a page mode device; S29PL032J is available as 48-ball FBGA only.
	Micron	ADP	2.7-3.6	2.7-3.6	64	M29DW640F	x8, x16	Boot Sector	60, 70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29JL064J S29PL064J	Yes	Yes	S29JL064J is not a page-mode device; S29PL064J is available as 48-ball FBGA only.
AMIC	Micron	ADP	2.7-3.6	2.7-3.6	64	M29DW641F	x16	Boot Sector	60, 70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29JL064J S29PL064J	Yes	Yes	S29JL064J is not a page mode device; S29PL064J is available as 48-ball FBGA only.
	Micron	ADP	2.7-3.6	2.7-3.6	128	M29DW128F	x8, x16	Boot Sector	60ns	56-Pin TSOP 64-Ball TBGA	0 to +70C -40 to +85C	S29PL127J	Yes	Yes	S29PL127J is pin compatible with 56-Pin TSOP.
Winbond	Micron	ADP	2.7-3.6	1.65-3.6	128	M29DW127G	x8, x16	Boot Sector	60, 70, 80ns	56-Pin TSOP 64-Ball TBGA	-40 to +85C	S29PL127J	Yes	Yes	Numonyx device access time is 80ns if full VIO is needed. S29PL127J is pin compatible with 56-Pin TSOP.
	Micron	ADP	2.7-3.6	1.65-3.6	128	M29DW128G	x16	Boot Sector	60, 70, 80ns	56-Pin TSOP 64-Ball TBGA	-40 to +85C	S29PL127J	Yes	Yes	Numonyx device access time is 80ns if full VIO is needed. S29PL127J is pin compatible with 56-Pin TSOP.
ESMT	Micron	ADP	2.7-3.6	1.65-3.6	256	M29DW256G	x16	Boot Sector	60, 70ns	56-Pin TSOP 64-Ball TBGA 64-Ball FBGA	0 to 70C -40 to +85C	S29GL256S	Yes	Yes	Numonyx device access time is 80ns if full VIO is needed. Pin compatible with S29GL256S x16 mode with no simul-op. Different sector architecture.
ESI, Chingis, GigaDevice	Micron	ADP	2.7-3.6	2.7-3.6	32	JR28F032M29EW PZ28F032M29EW	x8, x16	Uniform/ Boot Sector	60ns (BGA) 70ns (TSOP)	48-Pin TSOP 48-Ball BGA	-40 to +85C	S29GL032N	Yes	Yes	S29GL032N is pin-compatible with boot sector models.
	Micron	ADP	2.7-3.6	1.65-3.6	64	JR28F064M29EW JS28F064M29EW PC28F064M29EW PZ28F064M29EW	x8, x16	Uniform/ Boot Sector	60ns (BGA) 70ns (TSOP)	48-Pin TSOP 56-Pin TSOP 64-Ball FBGA 48-Ball BGA	-40 to +85C	S29GL064N	Yes	Yes	-
Micron, SST, EON, MCP	Micron	ADP	2.7-3.6	1.65-3.6	128	JS28F128M29EW PC28F128M29EW RC28F128M29EW	x8, x16	Uniform Sector	60ns (BGA) 70ns (TSOP)	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16.
NAND	Micron	ADP	2.7-3.6	1.65-3.6	256	JS28F256M29EW PC28F256M29EW RC28F256M29EW	x8 x16	Uniform Sector	100ns (FBGA) 110ns (TSOP)	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL256S S29GL256P	Yes	Yes	Spansion offers 90ns access time. S29GL256S supports x16-only. S29GL256P supports x8/x16.

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Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
	Micron	ADP	2.7-3.6	1.65-3.6	512	JS28F512M29EW PC28F512M29EW RC28F512M29EW	x8, x16	Uniform Sector	100ns (FBGA) 110ns (TSOP)	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL512S S29GL512P	Yes	Yes	Spansion offers 100ns access time. S29GL512S supports x16-only. S29GL512P supports x8/x16.
Macronix	Micron	ADP	2.7-3.6	1.65-3.6	1G	JS28F00AM29EW PC28F00AM29EW RC28F00AM29EW	x8, x16	Uniform Sector	100ns (FBGA) 110ns (TSOP)	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL01GS S29GL01GP	Yes	Yes	Spansion offers 100ns access time. S29GL01GS supports x16-only. S29GL01GP supports x8/x16.
Samsung	Micron	ADP	2.7-3.6	1.65-3.6	2G	JS28F00BM29EW PC28F00BM29EW RC28F00BM29EW	x8, x16	Uniform Sector	100ns (FBGA) 110ns (TSOP)	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S70GL02GS	Yes	Yes	Spansion offers 110ns access time. S70GL02GS supports x16-only. S70GL02GP supports x8/x16.
	Micron	ADP	2.3-3.6	2.3-3.6	64	JS28F640P33 PC28F640P33 RC28F640P33	x16	Boot sector	60ns (BGA) 70ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL064N	No	No	Different sector architecture pinouts and command set.
SST	Micron	ADP	2.3-3.6	2.3-3.6	128	JS28F128P33 PC28F128P33 RC28F128P33	x16	Boot sector	60ns (BGA) 70ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL128S	No	No	Different sector architecture pinouts and command set.
Atmel	Micron	ADP	2.3-3.6	2.3-3.6	256	JS28F256P33 PC28F256P33 RC28F256P33	x16	Boot sector	95ns (BGA) 105ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL256S	No	No	Different sector architecture pinouts and command set.
	Micron	ADP	2.3-3.6	2.3-3.6	512	JS28F512P33 PC28F512P33	x16	Uniform/ Boot Sector	95ns (BGA) 105ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL512S	No	No	Different pinouts and command set. S29GL512S has similar sector architecture for uniform sector models.
EON	Micron	ADP	2.3-3.6	2.3-3.6	1G	PC28F00AP33	x16	Uniform/ Boot Sector	95ns (BGA) 105ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL01GS	No	No	Different pinouts and command set. S29GL01GS has similar sector architecture for uniform sector models.
	Micron	ADP	2.3-3.6	2.3-3.6	2G	PC28F00BP33	x16	Uniform Sector	100ns	64-Ball Easy BGA	-40 to +85C	S29GL02GS	No	No	Different pinouts and command set. S29GL02GS has similar uniform sector architecture.
AMIC	Micron	ADP	2.3-3.6	2.3-3.6	64	PF48F2000POX	x16	Boot sector	85ns	88-Ball SCSP	-40 to +85C	S29GL064N	No	No	This Numonyx device is EOL. Different sector architecture pinouts and command set.
	Micron	ADP	2.3-3.6	2.3-3.6	128	RD48F3000POX	x16	Boot sector	85ns	88-Ball SCSP	-40 to +85C	S29GL128S	No	No	This Numonyx device is EOL. Different sector architecture pinouts and command set.
Winbond	Micron	ADP	2.3-3.6	2.3-3.6	256	PF48F4000POX RD48F4000POX	x16	Boot sector	85ns	88-Ball SCSP	-40 to +85C	S29GL256S	No	No	This Numonyx device is EOL. Different sector architecture pinouts and command set.
	Micron	ADP	2.3-3.6	2.3-3.6	512	PF48F4400POT RD48F4400POT	x16	Boot sector	85ns	64-Ball Easy BGA 88-Ball SCSP	-40 to +85C	S29GL512S	No	No	The SCSP devices are EOL. Different pinouts and command set. This Numonyx device is a dual-die stack. S29GL512S has similar sector architecture for uniform sector models.
ESMT	Micron	ADP	2.7-3.6	2.7-3.6	32	JS28F320J3 PC28F320J3 RC28F320J3	x8, x16	Uniform Sector	75ns	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL032N	No	No	Different pinouts and command set.
ESI, Chingis, GigaDevice	Micron	ADP	2.7-3.6	2.7-3.6	64	JS28F640J3 PC28F640J3 RC28F640J3	x8, x16	Uniform Sector	75ns	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL064N	No	No	Different pinouts and command set.
Micron, SST, EON, MCP	Micron	ADP	2.7-3.6	2.7-3.6	128	JS28F128J3 PC28F128J3 RC28F128J3	x8 x16	Uniform Sector	75ns	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL128S S29GL128P	No	No	Different pinouts and command set.
	Micron	ADP	2.7-3.6	2.7-3.6	256	JS28F256J3 TE28F256J3 PC28F256J3 RC28F256J3	x8 x16	Uniform Sector	95ns (BGA) 105ns (TSOP)	56-Pin TSOP 64-Ball Easy BGA	-40 to +85C	S29GL256S S29GL256P	No	No	Different pinouts and command set.
NAND															

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
	Micron	ADP	2.7-3.6	1.65-3.6	16	M28W160C	x16	Boot Sector	70, 90ns	48-Pin TSOP 46-Ball TFBGA	0 to 70C -40 to +85C	S29AL016J	No	No	Different sector architecture pinouts and command set.
Macronix	Micron	ADP	2.7-3.6	1.65-3.6	16	M28W160EC	x16	Boot Sector	70ns	48-Pin TSOP 46-Ball TFBGA	0 to 70C -40 to +85C	S29AL016J	No	No	Different sector architecture pinouts and command set.
	Micron	ADP	2.7-3.6	1.65-3.6	32	M28W320FC	x16	Boot Sector	70ns	48-Pin TSOP 47-Ball TFBGA	-40 to +85C	S29GL032N	No	No	Different pinout & command set
Samsung	Micron	ADP	2.7-3.6	1.65-3.6	64	M28W640FC	x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to 70C -40 to +85C	S29GL064N	Yes	No	Pin compatible with S29GL064N model numbers 06, 07, V6, V7 (48-Pin TSOP). Different sector architecture and command set.
	Micron	ADP	2.7-3.6	2.7-3.6	64	M28W640HC	x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29GL064N	Yes	No	Pin compatible with S29GL064N model numbers 06, 07, V6, V7 (48-Pin TSOP). Different sector architecture and command set.
SST	Micron	ADP	2.7-3.6	2.4-3.6	16	M58BW016D M58BW016F	x32	Boot Sector	70, 80ns	80-Pin PQFP 80-Ball LBGGA	-40 to 90C -40 to 125C	S29CL016J	Yes	No	Numonyx device does not have RY/BY# and has additional Burst Address Advance and Output Disable pins.
Atmel	Micron	ADP	2.7-3.6 2.5-3.3	2.4-3.6	16	M58BW16F	x32	Boot Sector	45, 55ns	80-Pin PQFP 80-Ball LBGGA	-40 to 125C	S29CD016J S29CL016J	Yes	No	45ns access only available with 2.7-3.6 voltage range for this Numonyx device. Numonyx device does not have RY/BY# replaces ACC with Program/Erase Enable and has additional Burst Address Advance and Output Disable pins.
EON	Micron	ADP	2.7-3.6 2.5-3.3	2.4-3.6	32	M58BW32F	x32	Boot Sector	45, 55ns	80-Pin PQFP 80-Ball LBGGA	-40 to 125C	S29CD032J S29CL032J	Yes	No	45ns access only available with 2.7-3.6 voltage range for this Numonyx device. Numonyx device does not have RY/BY# replaces ACC with Program/Erase Enable and has additional Burst Address Advance and Output Disable pins.
AMIC	Micron	ADP	4.5-5.5	-	2	M29F200F	x8, x16	Boot Sector	55ns	44-Pin SO 48-Pin TSOP	-40 to +85C -40 to +125C	Am29F200B	Yes	Yes	-
	Micron	ADP	4.5-5.5	-	4	M29F400F	x8, x16	Boot Sector	55ns	44-Pin SO 48-Pin TSOP	-40 to +85C -40 to +125C	Am29F400B	Yes	Yes	-
Winbond	Micron	ADP	4.5-5.5	-	8	M29F800F	x8, x16	Boot Sector	55ns	44-Pin SO 48-Pin TSOP 48-Ball TFBGA	-40 to +85C -40 to +125C	Am29F800B	Yes	Yes	-
	Micron	ADP	4.5-5.5	-	16	M29F160F	x8, x16	Boot Sector	55ns	48-Pin TSOP	-40 to +85C -40 to +125C	Am29F160D	Yes	Yes	-
ESMT	Micron	SPI	2.3-3.6	N/A	4	M25P40	x1	Uniform 64KB	75MHz	8-Pin SO 150mil/208mil, 8-Land SON 6x5 4x3 or 2x3	-40 to +85C -40 to +125C	S25FL204K	Yes	Yes	S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil. Spansion device supports 4KB sector size dual data output.
ESI, Chingis, GigaDevice	Micron	SPI	2.7-3.6	N/A	8	M25P80	x1	Uniform 64KB	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 or 4x3 8-Pin PDIP 300mil	-40 to +85C -40 to +125C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil. Spansion device supports 4KB sector size dual data output.
Micron, SST, EON, MCP	Micron	SPI	2.7-3.6	N/A	16	M25P16	x1	Uniform 64KB	75MHz	8-Pin SO 150mil/208mil 16-Pin SO 300mil 8-Land SON 8x6, 6x5 or 4x3 8-Pin PDIP 300mil	-40 to +85C -40 to +125C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. S25FL116K supports quad I/O. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K supports dual output.
NAND															

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
	Micron	SPI	2.7-3.6	N/A	32	M25P32	x1	Uniform 64KB	75MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Land SON 6x8	-40 to +85C -40 to +125C	S25FL032P	Yes	Yes	Package pinout sector size and core command set compatible.
Macronix	Micron	SPI	2.7-3.6	N/A	64	M25P64	x1	Uniform 64KB	75MHz	16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C -40 to +125C	S25FL064P	Yes	Yes	Package pinout sector size and core command set compatible.
Samsung	Micron	SPI	2.7-3.6	N/A	128	M25P128	x1	Uniform 256KB	75MHz	16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL128S	Yes	Yes	Package pinout sector size and core command set compatible. Spansion offers faster performance at 133MHz clock rate. Spansion also offers a uniform 64KB and 256KB sector device option. Spansion device supports quad I/O.
SST	Micron	SPI	2.7-3.6	N/A	4	M25PE40	x1	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL204K	No	Yes	Page Erase RESET# pin not supported by S25FL204K. Spansion device supports dual output
	Micron	SPI	2.7-3.6	N/A	8	M25PE80	x1	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL208K	No	Yes	Page Erase RESET# pin not supported by S25FL208K. Spansion device supports dual output.
Atmel	Micron	SPI	2.7-3.6	N/A	16	M25PE16	x1	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. S25FL116K supports quad I/O. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K supports dual output.
EON	Micron	SPI	2.3-3.6	N/A	8	M25PX80	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C -40 to +125C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
AMIC	Micron	SPI	2.3-3.6	N/A	16	M25PX16	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 24-Ball BGA 6x8 and 8-Land SON 6x5. S25FL116K supports quad I/O. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K supports dual output.
Winbond	Micron	SPI	2.7-3.6	N/A	32	M25PX32	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL032P	Yes	Yes	Package pinout sector size and core command set compatible.
ESMT	Micron	SPI	2.7-3.6	N/A	64	M25PX64	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Land SON 6x8 16-Pin SO 300mil 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL064P	Yes	Yes	Package pinout sector size and core command set compatible.
ESI, Chingis, GigaDevice	Micron	SPI	2.7-3.6	N/A	32	N25Q032	x1, x2, x4	Uniform 4KB /w 64KB Blocks	108MHz	8-Pin SO 150mil/208mil 16-Pin SO 300mil 8-Land SON 8x6, 6x5, 4x3 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-Pin SO 208mil, 16-Pin SO 300mil, 8-Land SON 8x6 or 6x5 and TFBGA 6x8. Core command set compatible.
Micron, SST, EON, MCP	Micron	SPI	2.7-3.6	N/A	64	N25Q064	x1, x2, x4	Uniform 4KB /w 64KB Blocks	108MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 8x6, 6x5 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-Pin SO 300mil, 8-Land SON 8x6 and TFBGA 6x8. Core command set compatible.
NAND	Micron	SPI	2.7-3.6	N/A	128	N25Q128	x1, x2, x4	Uniform 64KB /w 8 top/ bottom 4KB subsectors	108MHz	8-Land SON 6x8 16-Pin SO 300mil 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL128S	Yes	Yes	Package pinout and core command set compatible. Sector size compatible for Uniform 64KB models. S25FL128S has 133Mhz Fast Read Clock Frequency.

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Micron	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
	Micron	SPI	2.7-3.6	N/A	128	N25Q128A	x1, x2, x4	Uniform 64KB /w 8 top/ bottom 4KB subsectors	108MHz	8-Pin SO 208mil 8-Land SON 6x8, 6x5 16-Pin SO 300mil 24-Ball BGA 6x8	-40 to +85C -40 to +125C	S25FL128S	Yes	Yes	Core command set compatible. S25FL128S has 133Mhz Fast Read Clock Frequency.
Macronix	Micron	SPI	2.7-3.6	N/A	256	N25Q256	x1, x2, x4	Uniform 4KB /w 64KB Blocks	108MHz	16-Pin SO 300mil 8-Land SON 8x6 24-Ball BGA 6x8	-40 to +85C	S25FL256S	Yes	Yes	Core command set compatible. S25FL256S has 133Mhz Clock Frequency and higher DDR Fast dual and quad read frequencies.
Samsung	Micron	SPI	2.7-3.6	N/A	512	N25Q512	x1, x2, x4	Uniform 4KB /w 64KB Blocks	108MHz	16-Pin SO 300mil 8-Land SON 8x6 24-Ball BGA 6x8	-40 to +85C	S25FL512S	Yes	Yes	Core command set compatible. N25Q512 is stacked device (2x256Mb). S25FL512S has 133Mhz Clock Frequency and higher DDR Fast dual and quad read frequencies.
SST	Micron	SPI	2.7-3.6	N/A	1024	N25Q00A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	108MHz	16-Pin SO 300mil 24-Ball BGA 6x8	-40 to +85C	S70FL01GS	Yes	Yes	Core command set compatible. N25Q500A is a stacked device (4x256Mb). S70FL01GS has 133Mhz Clock Frequency and higher DDR Fast dual and quad read frequencies.
Atmel															
EON															
AMIC															
Winbond															
ESMT															
ESI, Chingis, GigaDevice															
Micron, SST, EON, MCP															
NAND															

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Macronix	ADP	1.65-2.2	-	8	MX29SL800C T/B MX29SL802C T/B	x8, x16	Boot Sector	90ns	48-Pin TSOP 48-Ball CSP-0.8mm pitch (TFBGA, LFBGA) 0.5mm pitch (WFBGA, XFLGA)	0 to 70C -40 to +85C	S29AS008J	Yes	Yes	Spansion S29AS008J is pin-compatible with 48-Pin TSOP, 48-Ball TFBGA, and 48-Ball LFBGA.
Samsung	Macronix	ADP	2.7-3.6 3.0-3.6	-	8	MX29LV800C	x8, x16	Boot Sector	45, 55, 70, 90ns	48-Pin TSOP 48-Ball T/LFBGA 44-Pin SOP	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	Macronix device does not have WP#. S29AL016J is pin-compatible with 48-Pin TSOP, 48-Ball TFBGA and 48-Ball LFBGA. Macronix device 45 and 55ns access times only available with restricted Vcc (3.0-3.6V).
SST	Macronix	ADP	2.7-3.6	-	16	MX29LV160D	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball T/LFBGA 48-Ball WFBGA/ XFLGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	S29AL016J is pin-compatible with 48-Pin TSOP, 48-Ball TFBGA and 48-Ball LFBGA.
Atmel	Macronix	ADP	2.7-3.6	1.65-3.6	16	MX29LV161D	x16	Boot Sector	90ns	48-Pin TSOP 48-Ball TFBGA 48-Ball WFBGA/ XFLGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	S29AL016J is pin-compatible with 48-Pin TSOP and 48-Ball TFBGA. MXIC replaces BYTE# with VIO.
EON	Macronix	ADP	2.7-3.6	-	32	MX29LV320D	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball T/LFBGA 44-Pin SOP	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	This Macronix device is EOL. S29GL032N is pin-compatible with 48-Pin TSOP, 48-Ball TFBGA and 48-Ball LFBGA. S29GL032N supports Page Mode. This Macronix device is EOL.
AMIC	Macronix	ADP	2.7-3.6	1.65-3.6	32	MX29LV321D	x16	Boot Sector	90ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	S29GL032N is pin-compatible with 48-Pin TSOP and 48-Ball TFBGA. Macronix replaces BYTE# with VIO. S29GL032N supports Page Mode. This Macronix device is not recommended for new designs.
Winbond	Macronix	ADP	2.7-3.6	-	32	MX29LV320E	x8, x16	Boot Sector	70, 90ns	44-Pin SOP 48-Pin TSOP 48-Ball T/LFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	S29GL032N is pin-compatible with 48-Pin TSOP, 48-Ball TFBGA and 48-Ball LFBGA. S29GL032N supports Page Mode.
ESMT	Macronix	ADP	2.7-3.6	-	64	MX29LV640D	x8, x16	Boot Sector	90ns	44-Pin SOP 48-Pin TSOP 48-Ball LFBGA	-40 to +85C 0 to +70C	S29GL064N	Yes	Yes	This Macronix device is EOL. S29GL064N is pin-compatible with 48-Pin TSOP and 48-Ball LFBGA. S29GL064N supports Page Mode. This Macronix device is EOL.
ESI, Chingis, GigaDevice	Macronix	ADP	2.7-3.6	-	64	MX29LV640E	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball FBGA	-40 to +85C 0 to +70C	S29GL064N	Yes	Yes	S29GL064N supports Page Mode.
Micron, SST, EON, MCP	Macronix	ADP	3.0-3.6	-	128	MX29LV128D	x8, x16	Uniform Sector	90ns	48-Pin TSOP 56-Pin TSOP 70-Pin SSOP	-40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S and S29GL128P are pin-compatible with 56-Pin TSOP. S29GL128S supports x16-only and Page Mode. S29GL128P supports x8/x16-only and Page Mode. This Macronix device is EOL.
NAND	Macronix	ADP	2.7-3.6	-	32	MX29GL320E	x8, x16	Boot/Uniform Sector	70ns	48-Pin TSOP 48-Ball LFBGA 56-Pin TSOP 64-Ball LFBGA	-40 to +85C	S29GL032N	Yes	Yes	-
	Macronix	ADP	2.7-3.6	-	64	MX29GL640E	x8, x16	Boot/Uniform Sector	70, 9ns	48-Pin TSOP 48-Ball LFBGA 56-Pin TSOP 64-Ball LFBGA	-40 to +85C	S29GL064N	Yes	Yes	-

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Macronix	ADP	2.7-3.6	1.65-3.6	128	MX29GL128E	x8, x16	Uniform Sector	90, 110ns	56-Pin TSOP 64-Ball FBGA 64-Ball LFBGA 70-Pin SSOP	-40 to +85C 0 to +70C	S29GL128S S29GL128P	Yes	Yes	S29GL128S and S29GL128P are pin compatible with 56-pin TSOP, 64-Ball FBGA. S29GL128S supports x16-only. S29GL128P supports x8/x16.
Macronix	Macronix	ADP	2.7-3.6	1.65-3.6	128	MX29GL128F	x8, x16	Uniform Sector	90, 110ns	56-Pin TSOP 56-Ball FBGA 64-Ball LFBGA	-40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16.
Samsung	Macronix	ADP	2.7-3.6 3.0-3.6	1.65-3.6	256	MX29GL256E	x8, x16	Uniform Sector	90, 100, 110ns	56-Pin TSOP 64-Ball FBGA 64-Ball LFBGA 70-Pin SSOP	-40 to +85C	S29GL256S S29GL256P	Yes	Yes	S29GL256S and S29GL256P are pin compatible with 56-pin TSOP, 64-Ball FBGA. S29GL256S supports x16-only. S29GL256P supports x8/x16. This Macronix device is not recommended for new designs.
SST	Macronix	ADP	2.7-3.6 3.0-3.6	1.65-3.6	256	MX29GL256F	x8, x16	Uniform Sector	90, 100, 110ns	56-Pin TSOP 56-Ball FBGA 64-Ball LFBGA	-40 to +85C	S29GL256S S29GL256P	Yes	Yes	S29GL256S supports x16-only. S29GL256P supports x8/x16.
Atmel	Macronix	ADP	2.7-3.6 3.0-3.6	-	512	MX29GL512E	x8, x16	Uniform Sector	100, 110ns	56-Pin TSOP 64-Ball LFBGA 70-Pin SSOP	-40 to +85C 0 to +70C	S29GL512S S29GL512P	Yes	Yes	S29GL512S and S29GL512P are pin compatible with 56-pin TSOP, 64-Ball LFBGA. S29GL512S supports x16-only. S29GL512P supports x8/x16. This Macronix device is not recommended for new designs.
EON	Macronix	ADP	2.7-3.6 3.0-3.6	1.65-3.6	512	MX29GL512F	x8, x16	Uniform Sector	100, 110ns	56-Pin TSOP 64-Ball LFBGA	-40 to +85C	S29GL512S S29GL512P	Yes	Yes	S29GL512S supports x16-only. S29GL512P supports x8/x16.
AMIC	Macronix	ADP	2.7-3.6	1.65-3.6	1G	MX68GL1G0F	x8, x16	Uniform Sector	110, 120ns	56-Pin TSOP 64-Ball LFBGA	-40 to +85C	S29GL01GS S29GL01GP	Yes	Yes	S29GL01GS supports x16-only. S29GL01GS supports x8/x16.
AMIC	Macronix	ADP	4.5-5.5	-	2	MX29F200CT/B	x8, x16	Boot Sector	70, 90ns	44-Pin SO 48-Pin TSOP 48-Pin RTSOP	-40 to +85C	Am29F200B	Yes	Yes	-
Winbond	Macronix	ADP	4.5-5.5	-	4	MX29F400CT/B	x8, x16	Boot Sector	70, 90ns	44-Pin SO 48-Pin TSOP	0 to +70C -40 to +85C	Am29F400B	Yes	Yes	-
Winbond	Macronix	ADP	4.5-5.5	-	4	MX29F040C	x8	Uniform Sector	70, 90ns	32-Pin PLCC 32-Pin TSOP	-40 to +85C	Am29F040B	Yes	Yes	-
ESMT	Macronix	ADP	4.5-5.5	-	8	MX29F800C T/B	x8, x16	Boot Sector	70, 90ns	44-Pin SO 48-Pin TSOP 48-Ball TFBGA	-40 to +85C	Am29F800B	Yes	Yes	-
ESI, Chingis, GigaDevice	Macronix	SPI	2.7-3.6	-	4	MX25L4005A	x1	Uniform 4KB /w 64KB Blocks	85MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 or 4x4 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL204K	Yes	Yes	This Macronix device is EOL.
Micron, SST, EON, MCP	Macronix	SPI	2.7-3.6	-	4	MX25L4005C	x1	Uniform 4KB /w 64KB Blocks	85MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	This Macronix device is EOL.
NAND	Macronix	SPI	2.7-3.6	-	4	MX25L4006E	x1, x2	Uniform 4K /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5, 2x3 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
NAND	Macronix	SPI	2.7-3.6	-	4	MX25L4025C	x1	Uniform 4KB /w 64KB Blocks	85MHz (@15pF) 66MHz (@30pF)	8-Pin SO 150mil	-40 to +85C	S25FL204K	Yes	Yes	This Macronix device is EOL.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
Micron	Macronix	SPI	2.7-3.6	-	4	MX25L4026E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 150mil	-40 to +85C	S25FL204K	Yes	Yes	S25FL204K is pin-compatible with 8-Pin SO 150mil.
	Macronix	SPI	2.3-3.6	-	4	MX25V4006E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 75MHz x2: 70MHz	8-Pin SO 150mil 8-Land SON 6x5	-40 to +85C	S25FL204K	Yes	Yes	S25FL204K is pin-compatible with 8-Pin SO 150mil.
	Macronix	SPI	2.3-3.6	-	4	MX25V4035	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 66MHz x2, x4: 50MHz	8-Pin SO 150mil 8-Land SON 6x5	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports dual output mode only. S25FL204K is pin-compatible with 8-Pin SO 150mil.
	Macronix	SPI	2.7-3.6	-	8	MX25L8005	x1	Uniform 4KB /w 64KB Blocks	86MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 or 4x4 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	Spansion device supports dual output. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil. This Macronix device is EOL.
	Macronix	SPI	2.7-3.6	-	8	MX25L8008E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 208mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 208mil.
	Macronix	SPI	2.7-3.6	-	8	MX25L8073E	x1, x2,x4	Uniform 4KB /w 64KB Blocks	x1,x4: 108MHz x2: 80MHz	8-Pin SO 208mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 208mil. Spansion device supports dual output mode only.
	Macronix	SPI	2.7-3.6	-	8	MX25L8075E	x1, x2,x4	Uniform 4KB /w 64KB Blocks	x1,x4: 108MHz x2: 80MHz	8-Pin SO 208mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 208mil. Spansion device supports dual output mode only.
	Macronix	SPI	2.7-3.6	-	8	MX25L8006E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 150mil/208mil, 8-Land SON 6x5, or 4x4 8-Pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
	Macronix	SPI	2.7-3.6	-	8	MX25L8035E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 108MHz x2: 80MHz (2.7-3.6V), 104MHz (3.0-3.6V) x4: 108MHz	8-Pin SO 208mil	-40 to +85C	S25FL208K	Yes	Yes	Core command set compatible. Pin-compatible with 8-Pin SO 208mil, Spansion device support dual output mode only.
	Macronix	SPI	2.7-3.6	-	8	MX25L8036E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	133MHz (@10pF)	8-Pin SO 208mil	-40 to +85C	S25FL208K	Yes	Yes	Core command set compatible. Spansion device support dual output mode only.
	Macronix	SPI	2.3-3.6	-	8	MX25V8006E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 75MHz x2: 70MHz	8-Pin SO 150mil 8-Land SON 6x5	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 150mil.
	Macronix	SPI	2.3-3.6	-	8	MX25V8035	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 66MHz x2, x4: 50MHz	8-Pin SO 150mil 8-Land SON 6x5	-40 to +85C	S25FL208K	Yes	Yes	Spansion device supports dual output mode only. S25FL208K is pin-compatible with 8-Pin SO 150mil.
	Macronix	SPI	2.7-3.6	-	16	MX25L1605D	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz (@15pF), 66MHz (@30pF) x2: 50MHz (@15pF)	8-Pin SO 150mil/208mil 16-Pin SO 300mil 8-Land SON 6x5, or 4x4 8-Pin PDIP 300mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil and 8-Land SON 6x5. This Macronix device is EOL.
	Macronix	SPI	2.7-3.6	-	16	MX25L1606E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 150mil/208mil 16-Pin SO 300mil 8-Land SON 6x5, or 4x4 8-Pin PDIP 300mil 24-Ball BGA	-40 to +85C	S25FL116K / S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 8-Land SON 6x5, and 24-Ball BGA. S25FL116K is quad output device. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil.
	Macronix	SPI	2.7-3.6	-	16	MX25L1608E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 208mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil. S25FL116K is quad output device.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Macronix	SPI	2.7-3.6	-	16	MX25L1633E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2,x4: 85MHz	8-Pin SO 208mil 8-Land SON 6x5, 4x4	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil and 8-Land SON 6x5.
Macronix	Macronix	SPI	2.7-3.6	-	16	MX25L1635D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 75MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil and 8-Land SON 6x5. This Macronix device is EOL.
Samsung	Macronix	SPI	2.7-3.6	-	16	MX25L1635E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 108MHz x2: 80MHz (2.7-3.6V), 104MHz (3.0-3.6V) x4: 108MHz	8-Pin SO 208mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil. Core command set compatible.
SST	Macronix	SPI	2.7-3.6	-	16	MX25L1636D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2,x4: 75MHz	8-Pin SO 208mil 16-Pin SO 300mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil.
SST	Macronix	SPI	2.7-3.6	-	16	MX25L1673E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 85MHz	8-Pin SO 208mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil.
Atmel	Macronix	SPI	2.7-3.6	-	16	MX25L1675E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 85MHz	8-Pin SO 208mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil.
Atmel	Macronix	SPI	2.7-3.6	-	16	MX25L1655D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 75MHz	8-Pin SO 208mil 24-Ball BGA	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil and 24-Ball BGA.
EON	Macronix	SPI	2.7-3.6	-	16	MX25L1636E	x1, x2, x4	Uniform 4KB /w 64KB Blocks	133MHz (@10pF)	8-Pin SO 208mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil.
AMIC	Macronix	SPI	2.7-3.6	-	32	MX25L3205D	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz (@15pF), 66MHz (@30pF) x2: 50MHz (@15pF)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5, or 4x4 8-Pin PDIP 300mil	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5. This Macronix device is EOL.
AMIC	Macronix	SPI	2.7-3.6	-	32	MX25L3206E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	8-Pin SO 208mil, 16-Pin SO 300mil 8-Land SON 6x5/4x4 8-Pin PDIP 300mil 24-BALL BGA	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO, 8-Land SON and 24-BALL BGA.
Winbond	Macronix	SPI	2.7-3.6	-	32	MX25L3225D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 75MHz	8-Pin SO 208mil	-40 to +85C	S25FL032P	Yes	Yes	Macronix part does not have HOLD#.
ESMT	Macronix	SPI	2.7-3.6	-	32	MX25L3235D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 75MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 or 8x6	-40 to +85C	S25FL032P	Yes	Yes	Macronix part does not have HOLD#.
ESI, Chingis, GigaDevice	Macronix	SPI	2.7-3.6	-	32	MX25L3236D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 75MHz	8-Pin SO 208mil	-40 to +85C	S25FL032P	Yes	Yes	Macronix part does not have HOLD#.
ESI, Chingis, GigaDevice	Macronix	SPI	2.7-3.6	1.65-2.7 2.7-3.6	32	MX25L3237D	x1, x2, x4	Uniform 4KB /w 64KB Blocks	VIO=2.7-3.6V: 86MHz x2 or x4 mode: 75MHz VIO=1.65-2.7V: 40MHz x2 or x4 mode: 33MHz	16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Macronix 16-Pin SO package uses pin 3 as VIO. Macronix 8-Land SON does not support x4 mode. Macronix part does not have HOLD#.
Micron, SST, EON, MCP	Macronix	SPI	2.7-3.6	-	32	MX25L3239E	x1, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1, x4: 104MHz	8-Pin SO 208mil 8-Pin VSOP 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Spansion device supports automotive temperature range. S25FL032P is pin-compatible with 8-pin SO and 8-Land SON 6x5.
NAND	Macronix	SPI	2.7-3.6	-	32	MX25L3235E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2: 86MHz x4: 104MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Spansion device supports automotive temperature range. S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Macronix	SPI	2.7-3.6	-	32	MX25L3275E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2: 86MHz x4: 104MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Spansion device supports automotive temperature range. S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5.
Macronix	Macronix	SPI	2.7-3.6	-	32	MX25L3237E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2: 86MHz x4: 104MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Spansion device supports automotive temperature range. S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5.
Samsung	Macronix	SPI	2.7-3.6	-	64	MX25L6405D	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz (@15pF) 66MHz (@30pF) x2: 50MHz (@15pF)	16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL064P	Yes	Yes	This Macronix device is EOL.
SST	Macronix	SPI	2.7-3.6	-	64	MX25L6439E	x1, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1/x4: 104MHz	8-Pin SO 208mil	-40 to +85C	S25FL064P	Yes	Yes	-
Atmel	Macronix	SPI	2.7-3.6	-	64	MX25L6406E	x1, x2	Uniform 4KB /w 64KB Blocks	x1: 86MHz x2: 80MHz	16-Pin SO 300mil 8-Pin SO 208mil 8-Land SON 6x8 24 Ball BGA	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO, 8-Land SON 6x8, 24-Ball BGA.
EON	Macronix	SPI	2.7-3.6	-	64	MX25L6436E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2: 70MHz x4: 75MHz	16-Pin SO 300mil 8-Pin SO 208mil 8-Land SON 6x8	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO and 8-Land SON 6x8. Macronix part does not have HOLD#.
AMIC	Macronix	SPI	2.7-3.6	-	64	MX25L6435E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 86MHz	16-Pin SO 300mil 8-Pin SO 208mil 8-Land SON 6x8 24 Ball BGA	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO, 8-Land SON 6x8, 24-Ball BGA.
Winbond	Macronix	SPI	2.7-3.6	-	64	MX25L6445E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 70MHz Double Transfer Rate x1, x2, x4: 50MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P does not support Macronix Double Transfer Rate Mode where address and data is latched on both SCK rising and falling edge. Macronix part does not have HOLD#.
ESMT	Macronix	SPI	2.7-3.6	-	64	MX25L6473E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1,x4: 104MHz x2: 86MHz	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL064P	Yes	Yes	-
ESI, Chingis, GigaDevice	Macronix	SPI	2.7-3.6	-	64	MX25L6475E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1,x4: 104MHz x2: 86MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO.
Micron, SST, EON, MCP	Macronix	SPI	2.7-3.6	-	64	MX25L6465E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2,x4: 70MHz Double Transfer Rate x1, x2, x4: 50MHz	8-Pin SO, 208mil 16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P does not support Macronix Double Transfer Rate Mode where address and data is latched on both SCK rising and falling edge. Macronix part does not have HOLD#.
NAND	Macronix	SPI	2.7-3.6	-	128	MX25L12805D	x1	Uniform 4KB /w 64KB Blocks	50MHz	16-Pin SO 300mil	-40 to +85C	S25FL128S	Yes	Yes	Spansion offers faster performance at 133MHz clock rate. This Macronix device is EOL.
	Macronix	SPI	2.7-3.6	-	128	MX25L12835F	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1,x2,x4: 133MHz	8-Pin SO 300mil 16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL128S	Yes	Yes	Spansion offers DDR scheme. Macronix part does not have HOLD#.
	Macronix	SPI	2.7-3.6	-	128	MX25L12835E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2,x4: 70MHz	16-Pin SO 300mil 8-Land SON 6x8/5x6	-40 to +85C	S25FL128S	Yes	Yes	Spansion offers faster performance at 133MHz x1 clock rate.
	Macronix	SPI	2.7-3.6	-	128	MX25L12836E	x1, x2, x4, Parallel x8	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 70MHz	16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL128S	Yes	Yes	Macronix part does not have HOLD#. Spansion offers 133MHz x1 clock rate and 104MHz x2, x4 clock rate.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
Micron	Macronix	SPI	2.7-3.6	-	128	MX25L12845E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 70MHz Double Transfer Rate x1, x2, x4: 50MHz	16-Pin SO, 300mil 8-Land SON 8x6	-40 to +85C	S25FL128S	Yes	Yes	Macronix part does not have HOLD#. Spansion offers 133MHz x1 clock rate, 104MHz x2, x4 clock rate, and 80MHz DDR.
Macronix	Macronix	SPI	2.7-3.6	-	128	MX25L12865E	x1, x2, x4, Parallel x8	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 70MHz Double Transfer Rate x1, x2, x4: 50MHz	16-Pin SO, 300mil 8-Land SON 8x6	-40 to +85C	S25FL128S	Yes	Yes	Macronix part does not have HOLD#. Spansion offers 133MHz x1 clock rate, 104MHz x2, x4 clock rate, and 80MHz DDR.
Samsung	Macronix	SPI	2.7-3.6	-	256	MX25L25635E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 80MHz x2, x4: 70MHz	16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL256S	Yes	Yes	Core command set compatible. Spansion device has DDR scheme and 133MHz x1 clock rate, 104MHz x2, x4 clock rate.
SST	Macronix	SPI	2.7-3.6	-	256	MX25L25735E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 80MHz x2, x4: 70MHz	16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL256S	Yes	Yes	Core command set compatible. Spansion device has DDR scheme and 133MHz x1 clock rate, 104MHz x2, x4 clock rate.
Atmel	Macronix	SPI	2.7-3.6	-	256	MX25L25835E	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 104MHz x2, x4: 70MHz	16-Pin SO 300mil	-40 to +85C	S25FL256S	Yes	Yes	Macronix device is a dual-die stack, uses two CS# pins. Spansion device has DDR scheme and 133MHz x1 clock rate, 104MHz x2, x4 clock rate.
EON	Macronix	SPI	2.7-3.6	-	256	MX25L25635F	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1, x2, x4: 133MHz	16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL256S	Yes	Yes	Core command set compatible. Spansion device has DDR scheme. Macronix part does not have HOLD#.
AMIC	Macronix	SPI	2.7-3.6	-	256	MX25L25639F	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1, x2: 133MHz	8-Land SON 8x6	-40 to +85C	S25FL256S	No	Yes	Spansion device has DDR scheme and 133MHz Clock Frequency.
Winbond	Macronix	SPI	2.7-3.6	-	512	MX66L51235F	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	133MHz	16-Pin SO 300mil 8-Land SON 8x6 24 Ball BGA	-40 to +85C	S25FL512S	Yes	Yes	Spansion device has DDR scheme and 133MHz Clock Frequency.
ESMT															
ESI, Chingis, GigaDevice															
Micron, SST, EON, MCP															
NAND															

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Samsung	ADP	1.7-1.95	-	32	K8A3215ETE K8A3215EBE	x16	Boot Sector/ 16 Banks	70ns/66MHz	MCP-only	-25 to +85C	S29WS064R	No	No	This Samsung device is EOL.
Macronix	Samsung	ADP	1.7-1.95	-	64	K8A6415ETB K8A6415EBB	x16	Boot Sector/ 16 Banks	70ns/66MHz	MCP-only	-25 to +85C	S29WS064R	No	No	This Samsung device is EOL.
Samsung	Samsung	ADP	1.7-1.95	-	64	K8A6415ETC K8A6415EBC	x16	Boot Sector/ 16 Banks	70ns/108MHz	88-Ball FBGA	-25 to +85C	S29WS064R	No	No	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	128	K8A2815ETB K8A2815EBB	x16	Boot Sector/ 16 Banks	70ns/66MHz	MCP-only	-25 to +85C	S29WS128P	No	Yes	This Samsung device is EOL.
SST	Samsung	ADP	1.7-1.95	-	128	K8A2815ETC	x16	Boot Sector/ 16 Banks	70ns/108MHz	MCP-only	-25 to +85C	S29WS128P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	128	K8A2615ETE	x16	Boot Sector/ 16 Banks	70ns/108MHz	MCP-only	-25 to +85C	S29WS128P	No	Yes	-
Atmel	Samsung	ADP	1.7-1.95	-	256	K8A5615ETA K8A5615EBA	x16	Boot Sector/ 16 Banks	70ns/66MHz	MCP-only	-25 to +85C	S29WS256P	No	Yes	-
	Samsung	ADP	1.7-1.95	-	256	K8A5515ETC	x16	Boot Sector/ 16 Banks	95ns/108MHz	MCP-only	-25 to +85C	S29WS256P	No	Yes	-
EON	Samsung	ADP	1.7-1.95	-	256	K8C5415ETM K8C5415EBM	x16	Boot Sector/ 16 Banks	100ns/83MHz	167-Ball FBGA	-25 to +85C	S29WS256P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	256	K8C5615ETM K8C5615EBM	x16	Boot Sector/ 16 Banks	100ns/83MHz	MCP-only	-25 to +85C	S29WS256P	No	Yes	This Samsung device is EOL.
AMIC	Samsung	ADP	1.7-1.95	-	256	K8C5715ETM K8C5715EBM	x16	Boot Sector/ 16 Banks	100ns/133MHz	167-Ball FBGA	-25 to +85C	S29WS256P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	256	K8C5615ETA K8C5615EBA	x16	Boot Sector/ 16 Banks	100ns/83MHz	44-Ball FBGA 88-Ball FBGA	-25 to +85C	S29WS256P	No	Yes	This Samsung device is EOL.
Winbond	Samsung	ADP	1.7-1.95	-	256	K8C5715ETA K8C5715EBA	x16	Boot Sector/ 16 Banks	100ns/133MHz	44-Ball FBGA 88-Ball FBGA	-25 to +85C	S29WS256P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	512	K8C1015ETM K8C1015EBM	x16	Boot Sector/ 16 Banks	110ns/83MHz	167-Ball FBGA	-25 to +85C	S29WS512P	No	Yes	This Samsung device is EOL.
ESMT	Samsung	ADP	1.7-1.95	-	512	K8C1215ETM K8C1215EBM	x16	Boot Sector/ 16 Banks	110ns/83MHz	167-Ball FBGA	-25 to +85C	S29WS512P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	512	K8C1315ETM K8C1315EBM	x16	Boot Sector/ 16 Banks	110ns/133MHz	167-Ball FBGA	-25 to +85C	S29WS512P	No	Yes	This Samsung device is EOL.
ESI, Chingis, GigaDevice	Samsung	ADP	1.7-1.95	-	512	K8C1215EBA	x16	Boot Sector/ 16 Banks	110ns/83MHz	64-Ball FBGA	-25 to +85C	S29WS512P	No	Yes	This Samsung device is EOL.
	Samsung	ADP	1.7-1.95	-	512	K8C1315ETA	x16	Boot Sector/ 16 Banks	110ns/133MHz	64-Ball FBGA	-25 to +85C	S29WS512P	No	Yes	This Samsung device is EOL.
Micron, SST EON MCP	Samsung	ADM	1.7-1.95	-	32	K8S3215ETD	x16	Boot Sector/ 16 Banks	90ns/54MHz	44-Ball FBGA	-45 to +85C	S29VS064R	Yes	Yes	This Samsung device is EOL.
	Samsung	ADM	1.7-1.95	-	32	K8S3215ETE K8S3215EBE	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-25 to +85C	S29VS064R	Yes	Yes	This Samsung device is EOL.
NAND	Samsung	ADM	1.7-1.95	-	32	K8S3215ETF K8S3215EBF	x16	Boot Sector/ 16 Banks	70ns/108MHz	44-Ball FBGA	-25 to +85C	S29VS064R	Yes	Yes	This Samsung device is EOL.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Samsung	ADM	1.7-1.95	-	64	K8S6415ETB K8S6415EBB	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-25 to +85C	S29VS064R	Yes	Yes	This Samsung device is EOL.
Macronix	Samsung	ADM	1.7-1.95	-	64	K8S6415ETC	x16	Boot Sector/ 16 Banks	70ns/108MHz	MCP-only	-25 to +85C	S29VS064R	No	Yes	This Samsung device is EOL.
Samsung	Samsung	ADM	1.7-1.95	-	64	K8S6015ETD	x16	Boot Sector	70ns/66MHz	44-Ball FBGA	-25 to +85C	S29VS064R	Yes	Yes	This Samsung device is EOL.
	Samsung	ADM	1.7-1.95	-	64	K8S6615ETD	x16	Boot Sector/ 8 Banks	70ns/108MHz	44-Ball FBGA	-25 to +85C	S29VS064R	Yes	Yes	S29VS064R has 4 banks.
SST	Samsung	ADM	1.7-1.95	-	128	K8S2815ETB K8S2815EBB	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-25 to +85C	S29VS128R	Yes	No	This Samsung device is EOL. S29VS128R has simplified command set. S29VS128R has 8 banks.
	Samsung	ADM	1.7-1.95	-	128	K8S2815ETC K8S2815EBC	x16	Boot Sector/ 16 Banks	70ns/108MHz	44-Ball FBGA	-25 to +85C	S29VS128R	Yes	No	This Samsung device is EOL. S29VS128R has simplified command set. S29VS128R has 8 banks.
	Samsung	ADM	1.7-1.95	-	128	K8S2615ETE	x16	Boot Sector/ 16 Banks	70ns/108MHz	44-Ball FBGA	-25 to +85C	S29VS128R	Yes	No	S29VS128R has simplified command set. S29VS128R has 8 banks.
Atmel	Samsung	ADM	1.7-1.95	-	256	K8S5615ETA K8S5615EBA	x16	Boot Sector/ 16 Banks	70ns/66MHz	44-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	This Samsung device is EOL. Spansion offers faster burst speed. S29VS256R has simplified command set. S29VS256R has 8 banks.
	Samsung	ADM	1.7-1.95	-	256	K8S5515ETC	x16	Boot Sector/ 16 Banks	95ns/108MHz	44-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	S29VS256R has simplified command set. S29VS256R has 8 banks.
EON	Samsung	ADM	1.7-1.95	-	512	K8S1115ETC	x16	Boot Sector/ 16 Banks	95ns/108MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	-
	Samsung	ADM	1.7-1.95	-	256	K8F5615ETM K8F5615EBM	x16	Boot Sector/ 16 Banks	100ns/83MHz	44-Ball FBGA 88-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	This Samsung device is EOL. S29VS256R has simplified command set. S29VS256R has 8 banks.
AMIC	Samsung	ADM	1.7-1.95	-	256	K8F5715ETM K8F5715EBM	x16	Boot Sector/ 16 Banks	100ns/133MHz	44-Ball FBGA 88-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	This Samsung device is EOL. S29VS256R has simplified command set. S29VS256R has 8 banks.
	Samsung	ADM	1.7-1.95	-	256	K8F5615ETA K8F5615EBA	x16	Boot Sector/ 16 Banks	100ns/83MHz	44-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	This Samsung device is EOL. S29VS256R has simplified command set. S29VS256R has 8 banks.
Winbond	Samsung	ADM	1.7-1.95	-	256	K8F5715ETA K8F5715EBA	x16	Boot Sector/ 16 Banks	100ns/133MHz	44-Ball FBGA	-25 to +85C	S29VS256R	Yes	No	This Samsung device is EOL. S29VS256R has simplified command set. S29VS256R has 8 banks.
	Samsung	ADM	1.7-1.95	-	512	K8F1215ETM K8F1215EBM	x16	Boot Sector/ 16 Banks	110ns/83MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	This Samsung device is EOL.
ESMT	Samsung	ADM	1.7-1.95	-	512	K8F1315ETM K8F1315EBM	x16	Boot Sector/ 16 Banks	110ns/133MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	This Samsung device is EOL.
	Samsung	ADM	1.7-1.95	-	512	K8F1215EBA	x16	Boot Sector/ 16 Banks	110ns/83MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	This Samsung device is EOL.
ESI, Chingis, GigaDevice	Samsung	ADM	1.7-1.95	-	512	K8F1315ETA	x16	Boot Sector/ 16 Banks	110ns/133MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	This Samsung device is EOL.
	Samsung	ADM	1.7-1.95	-	512	K8F1115EBM	x16	Boot Sector/ 16 Banks	100ns/108MHz	64-Ball FBGA	-25 to +85C	S29NS512P	Yes	Yes	This Samsung device is EOL.
Micron, SST, EON, MCP	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	16	K8P1615UQB	x16	Dual Boot Sector/4 Banks	60ns	48-Pin TSOP 48-Ball FBGA	-25 to +85C -40 to +85C	S29PL032J S29JL032J	Yes	Yes	This Samsung device is EOL. Different sector architecture. S29JL032J is not a page-mode device. S29PL032J is available as 48-ball FBGA only.
	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	32	K8P3215UQB	x16	Dual Boot Sector/4 Banks	55ns	48-Pin TSOP 48-Ball FBGA 64-Ball FBGA	-25 to +85C -40 to +85C	S29PL032J S29JL032J	Yes	Yes	This Samsung device is EOL. Different sector architecture to S29JL032J. S29JL032J is not a page-mode device. S29PL032J is available as 48-ball FBGA only.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	32	K8P3315UQB	x16	Dual Boot Sector/8 Banks	60ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -25 to +85C -40 to +85C	S29PL032J S29JL032J	Yes	Yes	This Samsung device is EOL. Different bank architecture. S29JL032J is not a page-mode device. S29PL032J is available as 48-ball FBGA only.
Macronix	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	64	K8P6415UQB	x16	Dual Boot Sector/4 Banks	60ns	48-Pin TSOP 48-Ball FBGA 64-Ball FBGA	-25 to +85C -40 to +85C	S29PL064J S29JL064J	Yes	Yes	This Samsung device is EOL. S29JL064J is not a page-mode device. S29PL064J is available as 48-ball FBGA only.
Samsung	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	64	K8P6515UQB	x16	Dual Boot Sector/8 Banks	60ns	48-Pin TSOP 48-Ball FBGA 64-Ball FBGA	-25 to +85C	S29PL064J S29JL064J	Yes	Yes	This Samsung device is EOL. S29JL064J is not a page-mode device. S29PL064J is available as 48-ball FBGA only.
SST	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	128	K8Q2815UQB	x16	Dual Boot Sector/8 Banks	60ns	56-Pin TSOP	-25 to +85C -40 to +85C	S29GL128S	Yes	Yes	This Samsung device is EOL. Different sector sizes. S29GL128S is a monolithic, single bank device. This Samsung device is a 2-die, multibank device.
Atmel	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	128	K8P2815UQB	x16	Dual Boot Sector/4 Banks	60ns	64-Ball FBGA 80-Ball FBGA	-25 to +85C -40 to +85C	S29PL127J S29GL128S	Yes	Yes	This Samsung device is EOL. S29PL127J is pin-compatible with 80-Ball FBGA. S29PL127J offers faster access speeds. S29GL128S is pin-compatible with 64-Ball FBGA. S29GL128S is a single bank device.
EON	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	128	K8P2915UQB	x16	Boot Sector	60ns	64-Ball FBGA 80-Ball FBGA	-25 to +85C	S29PL127J	Yes	Yes	This Samsung device is EOL. Samsung device is a dual-CE# device. The 2nd CE# is equal to AMAX on S29PL127J.
AMIC	Samsung	ADP	2.7-3.6	1.7-3.6 2.7-3.6	128	K8P2716UZC	x8, x16	Uniform Sector	65, 70, 80ns	64-Ball FBGA 56-Pin TSOP	-25 to +85C -40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16.
	Samsung	ADP	2.7-3.6	1.65-1.95 2.7-3.6	128	K8P2815UQC	x16	Dual Boot Sector/4 Banks	65, 70ns	64-Ball FBGA 80-Ball FBGA 56-Pin TSOP	-25 to +85C -40 to +85C	S29PL127J S29GL128S	Yes	Yes	S29GL128P supports x8/x16.
Winbond	Samsung	ADP	2.7-3.6	1.65-3.6	256	K8P5515UZB	x16	Uniform Sector	80ns	56-Pin TSOP 64-Ball FBGA	-25 to +85C -40 to +85C	S29GL256S	Yes	Yes	-
ESMT	Samsung	ADP	2.7-3.6	2.7-3.6	256	K8P5616UZB	x8, x16	Uniform Sector/4 Banks	80ns	56-Pin TSOP 64-Ball FBGA	-25 to +85C -40 to +85C	S29GL256S S29GL256P	Yes	Yes	S29GL256S supports x16-only. S29GL256P supports x8/x16. Both GL-S and GL-P are single-bank devices.
	Samsung	ADP	2.7-3.6	2.7-3.6	256	K8P5615UQA	x16	Dual Boot Sector/4 Banks	70ns	56-Pin TSOP 84-Ball FBGA	-25 to +85C -40 to +85C	S29GL256S	Yes	Yes	This Samsung device is EOL. S29GL256S is pin-compatible with 56-Pin TSOP. S29GL256S is a single bank device. This Samsung device is a multibank device.
ESI, Chingis, GigaDevice	Samsung	ADP	2.7-3.6	2.7-3.6	512	K8Q1116UZB	x8, x16	Uniform Sector	80ns	64-Ball FBGA	-40 to +85C	S29GL512S S29GL512P	Yes	Yes	This Samsung device is EOL. S29GL512S supports x16-only. S29GL512P supports x8/x16. Both GL-S and GL-P are monolithic devices. This Samsung device is a 2-die stack.
Micron, SST, EON, MCP	Samsung	ADP	2.7-3.6	2.7-3.6	16	K8D1716UTC K8D1716UBC	x8, x16	Boot Sector/ 2 Banks	70ns	48-Ball FBGA 48-Pin TSOP	-40 to +85C	S29AL016J	Yes	Yes	This Samsung device is EOL. S29AL016J is a single-bank device.
	Samsung	ADP	2.7-3.6	2.7-3.6	32	K8D3216UTC K8D3216UBC	x8, x16	Boot Sector/ 2 Banks	70ns	48-Ball FBGA 48-Pin TSOP	-40 to +85C	S29JL032J	Yes	Yes	This Samsung device is EOL.
NAND	Samsung	ADP	2.7-3.6	2.7-3.6	64	K8D6316UTM K8D6316UBM	x8, x16	Boot Sector/ 2 Banks	70ns	48-Ball FBGA 48-Pin TSOP	-40 to +85C	S29JL064J	Yes	Yes	This Samsung device is EOL.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	SST	ADP	1.65-1.95	-	8	SST39WF800A	x16	Uniform Sector	90ns	48-Ball BGA 48-Ball WFBGA 48-Bump FLGA	0 to 70C -40 to +85C	S29AS008J	Yes	Yes	This SST device is EOL. Spansion S29AS008J is pin-compatible with 48-Ball TFBGA. SST device does not have RESET#, RY/BY#, or BYTE# and has different sector sizes.
Macronix	SST	ADP	1.65-1.95	-	8	SST39WF800B	x16	Uniform Sector	70ns	48-Ball BGA 48-Ball WFBGA 48-Bump FLGA	0 to 70C -40 to +85C	S29AS008J	Yes	Yes	Spansion S29AS008J is pin-compatible with 48-Ball TFBGA. SST device does not have RESET#, RY/BY#, or BYTE# pins and has different sector sizes.
Samsung	SST	ADP	1.65-1.95	-	16	SST39WF1601/2	x16	Uniform Sector	70, 90ns	48-Ball TFBGA 48-Ball WFBGA	0 to 70C -40 to +85C	S29AS016J	Yes	Yes	Spansion S29AS016J is pin-compatible with 48-Ball TFBGA. SST device does not have RY/BY#, or BYTE# pins and has different sector sizes. This SST device is EOL.
SST	SST	ADM	1.7-1.95	-	16	SST34WA1601/2	x16	Boot Sector/ 4 Banks	70ns/66MHz	44-Ball FBGA	-20 to +85C	S29VS064R	Yes	Yes	This SST device is EOL.
	SST	ADM	1.7-1.95	-	32	SST34WA3203/4	x16	Boot Sector/ 4 Banks	70ns/66MHz	44-Ball FBGA	-20 to +85C	S29VS064R	Yes	Yes	This SST device is EOL.
Atmel	SST	ADP	2.7-3.6	-	8	SST39VF800A	x16	Uniform Sector	70ns	48-Pin TSOP 48-Ball TFBGA 48-Ball WFBGA/ XFLGA	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block.
EON	SST	ADP	3.0-3.6	-	8	SST39LF800A	x16	Uniform Sector	55ns	48-Pin TSOP 48-Ball TFBGA 48-Ball WFBGA/ XFLGA	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block.
	SST	ADP	2.7-3.6	-	8	SST39VF801C/2C	x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA 48-Ball WFBGA	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size. SST device does not have BYTE#.
AMIC	SST	ADP	2.7-3.6	-	16	SST39VF1601C/2C	x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA 48-Ball WFBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size. SST device does not have BYTE#.
Winbond	SST	ADP	2.7-3.6	-	16	SST39VF1601/2	x16	Uniform Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. SST device does not have RY/BY# and BYTE# pins.
ESMT	SST	ADP	2.7-3.6	-	16	SST39VF1681/2	x8	Uniform Sector	70, 90ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block.
	SST	ADP	2.7-3.6	-	32	SST39VF3201/2	x16	Uniform Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. SST device does not have RY/BY# and BYTE# pins.
ESI, Chingis, GigaDevice	SST	ADP	2.7-3.6	-	32	SST39VF3201B/2B	x16	Uniform Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size.
	SST	ADP	2.7-3.6	-	32	SST39VF3201C/2C	x16	Uniform Sector	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size.
Micron, SST EON MCP	SST	ADP	2.7-3.6	-	64	SST39VF6401B/2B	x16	Uniform Sector	70, 90ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C 0 to +70C	S29GL064N	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size.
NAND	SST	ADP	2.7-3.6	-	64	SST38VF6401/2/3/4	x16	Uniform/ Boot Sector	90ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C 0 to +70C	S29GL064N	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. Spansion sector size is equivalent to SST block size.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	SST	ADP	2.7-3.6	-	16	SST36VF1601/2E	x8, x16	Uniform Sector/ 2 Banks	70ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. SST device is Simul-Op. This SST device is EOL.
Macronix	SST	ADP	2.7-3.6	-	16	SST36VF1601/2G	x8, x16	Uniform Sector/ 2 Banks	70ns	48-Pin TSOP 48-Ball TFBGA 56-Ball LFBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	Different sector architecture. SST supports 4KB sectors with 64KB overlay block. SST device is Simul-Op. This SST device is EOL.
Samsung	SST	ADP	2.7-3.6	-	32	SST36VF3203/4	x8, x16	Boot Sector/ 2 Banks	70ns	48-Pin TSOP 48-Ball TFBGA	-20 to +85C -40 to +85C	S29JL032J S29PL032J	Yes	Yes	Different bank/sector architecture. SST supports 4KB sectors with 64KB overlay block. S29JL032J is available in 48-pin TSOP, no page-mode. S29PL032J has page mode and available as 48-ball FBGA. This SST device is EOL.
SST	SST	ADP	4.5-5.5	-	512K	SST29EE512	x8	Uniform Sector	70ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F010B	Yes	Yes	-
	SST	ADP	4.5-5.5	-	1	SST29EE010	x8	Uniform Sector	70, 90ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F010B	Yes	Yes	This SST device is EOL.
Atmel	SST	ADP	4.5-5.5	-	1	SST39SF010A	x8	Uniform Sector	45, 70ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F010B	Yes	Yes	-
	SST	ADP	4.5-5.5	-	2	SST39SF020A	x8	Uniform Sector	45, 70ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F002NB	Yes	Yes	-
EON	SST	ADP	4.5-5.5	-	2	SST29SF020	x8	Uniform Sector	55ns	32-Pin PLCC 32-Pin TSOP	0 to +70C -40 to +85C	Am29F002NB	Yes	Yes	-
	SST	ADP	4.5-5.5	-	4	SST39SF040	x8	Uniform Sector	45, 70ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F040B	Yes	Yes	-
AMIC	SST	ADP	4.5-5.5	-	4	SST29SF040	x8	Uniform Sector	55ns	32-Pin PLCC 32-Pin TSOP	0 to +70C -40 to +85C	Am29F040B	Yes	Yes	This SST device is EOL.
	SST	SPI	2.7-3.6	-	4	SST25VF040B	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5	0 to +70C -40 to +85C	S25FL204K	Yes	Yes	S25FL204K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil/208mil.
Winbond	SST	SPI	2.7-3.6	-	8	SST25VF080B	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	S25FL208K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil/208mil.
	SST	SPI	2.7-3.6	-	16	SST25VF016B	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Land SON 6x5	0 to +70C -40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad i/o feature and is pin-compatible with 8-Pin SO and 8-Land SON 6x5. S25FL216K supports dual output feature and is pin-compatible with 8-Pin SO 208mil.
ESI, Chingis, GigaDevice	SST	SPI	2.7-3.6	-	16	SST26VF016	x1, x4	Uniform 4KB /w 8x8KB 2x32KB & 30x64KB Blocks	80MHz	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad i/o feature and is pin-compatible with 8-Pin SO and 8-Land SON 6x5. S25FL216K supports dual output feature and is pin-compatible with 8-Pin SO 208mil.
	SST	SPI	2.7-3.6	-	32	SST25VF032B	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible.
Micron, SST EON MCP	SST	SPI	2.7-3.6	-	32	SST26VF032	x1, x4	Uniform 4KB /w 8x8KB 2x32KB & 62x64KB Blocks	80MHz	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible SST device offers individual block protection. SST device does not have HOLD#.
	SST	SPI	2.7-3.6	-	64	SST25VF064C	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1: 80MHz x2: 75MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 8x6	0 to +70C -40 to +85C	S25FL064P	Yes	Yes	Package, pinout and core command set compatible.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Atmel	SPI	2.3-3.6 2.7-3.6	-	4	AT25DF041A	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	70MHz (2.7-3.6V) 50MHz (2.3-3.6V)	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports dual output. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
Macronix	Atmel	SPI	2.7-3.6	-	8	AT25DF081A	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	70MHz	8-Pin SO 150mil/208mil	-40 to +85C	S25FL208K	Yes	Yes	Spansion device supports dual output. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
Samsung	Atmel	SPI	2.3-3.6 2.7-3.6	-	16	AT25DF161	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2: 85MHz (@15pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad i/o feature and is pin-compatible with 8-Pin SO and 8-Land SON 6x5. S25FL216K supports dual output feature and is pin-compatible with 8-Pin SO 208mil. Atmel device has RapidS mode which is a non- standard SPI -based operation.
SST	Atmel	SPI	2.7-3.6	-	16	AT25DQ161	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2, x4: 85MHz (@15pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad i/o feature and is pin-compatible with 8-Pin SO and 8-Land SON 6x5. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. Atmel device has RapidS mode which is a non-standard SPI -based operation.
Atmel	Atmel	SPI	2.7-3.6	-	32	AT25DQ321A	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2, x4: 85MHz (@15pF)	8-Pin SO 150mil/208mil 16-pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Atmel offers individual 64KB block protection. Atmel device has RapidS mode which is a non- standard SPI -based operation. Spansion device support dual output mode only.
EON	Atmel	SPI	2.7-3.6	-	32	AT25DF321A	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2: 85MHz (@15pF)	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Atmel offers individual 64KB block protection. Atmel device has RapidS mode which is a non- standard SPI -based operation.
AMIC	Atmel	SPI	2.7-3.6	-	32	AT25DF321	x1	Uniform 4KB /w 32KB Blocks & 64KB Blocks	70MHz (@15pF) 66MHz (@30pF)	8-Pin SO 208mil 16-Pin SO 300mil	-40 to +85C	S25FL032P	Yes	Yes	Atmel offers individual 64KB block protection. This Atmel device is EOL.
	Atmel	SPI	2.7-3.6	-	64	AT25DF641A	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2: 85MHz (@15pF)	8-Pin SO 208mil 8-Land SON 6x5	-40 to +85C	S25FL064P	Yes	Yes	Atmel offers individual 64KB block protection. Atmel device has RapidS mode which is a non- standard SPI -based operation.
Winbond	Atmel	SPI	2.7-3.6	-	64	AT25DF641	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	RapidS: 100MHz (@15pF) x1, x2: 85MHz (@15pF)	8-Land SON 6x8 16-Pin SO 300mil	-40 to +85C	S25FL064P	Yes	Yes	Atmel offers individual 64KB block protection. Atmel device has RapidS mode which is a non- standard SPI -based operation.
ESMT															
ESI, Chingis, GigaDevice															
Micron, SST EON MCP															
NAND															

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	EON	ADP	1.65-1.95	-	8	EN39SL800	x16	Uniform Sector	70ns	48-Ball TFBGA 48-Ball WFBGA	-40 to +85C	S29AS008J	Yes	Yes	Spansion S29AS008J is pin-compatible with 48-Ball TFBGA. EON device does not have RESET#, RY/BY#, BYTE#, and WP#. EON device has 64KB blocks with 4KB sectors.
Macronix	EON	ADP	1.65-1.95	-	8	EN39SL801	x16	Uniform Sector	70ns	48-Ball TFBGA 48-Ball WFBGA	-40 to +85C -40 to +125C	S29AS008J	Yes	Yes	Spansion S29AS008J is pin-compatible with 48-Ball TFBGA. EON device does not have RY/BY#, BYTE#, and WP#. EON device has 64KB blocks with 4KB sectors.
Samsung	EON	ADP	1.65-1.95	-	16	EN39SL160AL	x16	Uniform Sector	70ns	48-Ball TFBGA 48-Ball WFBGA	-40 to +85C	S29AS016J	Yes	Yes	Spansion S29AS016J is pin-compatible with 48-Ball TFBGA and 48-Ball WFBGA. EON device does not have RY/BY# and BYTE#. EON device has 64KB blocks with 4KB sectors.
SST	EON	ADP	2.7-3.6	-	8	EN29LV800B	x8, x16	Boot Sector	55, 70, 90ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	This EON device is EOL. EON device does not have WP#.
	EON	ADP	2.7-3.6	-	8	EN29LV800C	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C -45 to +125C	S29AL008J	Yes	Yes	EON device does not have WP#.
Atmel	EON	ADP	2.7-3.6	-	16	EN29LV160B	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29AL016J	Yes	Yes	This EON device is EOL. EON device does not have WP#.
	EON	ADP	2.7-3.6	-	16	EN29LV160C	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29AL016J	Yes	Yes	EON device does not have WP#.
EON	EON	ADP	2.7-3.6	-	32	EN29LV320B	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29GL032N	Yes	Yes	S29GL032N supports page mode.
	EON	ADP	2.7-3.6	-	32	EN29LV320C	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball TFBGA	-40 to +85C	S29GL032N	Yes	Yes	S29GL032N supports page mode.
AMIC	EON	ADP	2.7-3.6	-	64	EN29LV640A	x8, x16	Boot Sector	90ns	48-Pin TSOP 48-Ball FBGA	-40 to +85C	S29GL064N	Yes	Yes	S29GL064N supports page mode.
	EON	ADP	2.7-3.6	1.65-3.6	64	EN29GL064	x8, x16	Uniform Sector	70ns	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL064N	Yes	Yes	-
Winbond	EON	ADP	2.7-3.6	-	64	EN29GL064A	x8, x16	Boot Sector	70ns	48-Pin TSOP 48-Ball FBGA	-40 to +85C	S29GL064N	Yes	Yes	-
	EON	ADP	2.7-3.6	1.65-3.6	128	EN29GL128	x8/x16	Uniform Sector	70ns	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL128S S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16.
ESMT	EON	ADP	2.7-3.6	1.65-3.6	256	EN29GL256	x8/x16	Uniform Sector	90ns	56-Pin TSOP 64-Ball FBGA	-40 to +85C	S29GL256S S29GL256P	Yes	Yes	S29GL256S supports x16-only. S29GL256P supports x8/x16.
	EON	SPI	2.3-3.6	-	4	EN25F40	x1	Uniform 4KB /w 64KB Blocks	100MHz (@20pF) 75MHz (@30pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL204K	Yes	Yes	Spansion device supports dual output. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
ESI, Chingis, GigaDevice	EON	SPI	2.7-3.6	-	4	EN25Q40	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 100MHz (@20pF) x2, x4: 80MHz (@30pF)	8-Pin SO 150mil 8-Land SON 6x5 8-Land SON 2x3	-40 to +85C	S25FL204K	No	Yes	Spansion device supports single I/O and dual output. S25FL204K is pin-compatible with 8-Pin SO 150mil. EON device does not have HOLD#.
Micron, SST, EON, MCP	EON	SPI	2.7-3.6	-	8	EN25F80	x1	Uniform 4KB /w 64KB Blocks	100MHz (@20pF) 75MHz (@30pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	Spansion device supports dual output. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
NAND	EON	SPI	2.7-3.6	-	8	EN25Q80A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 100MHz (@20pF) x2, x4: 80MHz (@30pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL208K	No	Yes	Spansion device supports single I/O and dual output. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil. EON device does not have HOLD#.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	EON	SPI	2.7-3.6	-	16	EN25F16	x1	Uniform 4KB /w 64KB Blocks	100MHz (@20pF) 75MHz (@30pF)	8-Pin SO 150mil/208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad I/O and is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. S25FL216K supports single I/O and dual output only and is pin-compatible with 8-Pin SO 150mil/208mil. EON device does not have HOLD#.
Macronix	EON	SPI	2.7-3.6	-	16	EN25Q16	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 100MHz (@20pF) x2, x4: 80MHz (@30pF)	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. EON device does not have HOLD#. This EON device is EOL.
Samsung	EON	SPI	2.7-3.6	-	16	EN25Q16A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. EON device does not have HOLD#. This EON device is EOL.
SST	EON	SPI	2.7-3.6	-	16	EN25QH16	x1, x2, x4	Uniform 4KB /w 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil 24-Ball BGA 6x8	-40 to +85C	S25FL116K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 8-Land SON 6x5, and 24-Ball BGA 6x8. EON device does not have HOLD#. This EON device is EOL.
Atmel	EON	SPI	2.7-3.6	-	32	EN25P32	x1	Uniform 64KB	100MHz (@20pF, 3.0-3.6V) 75MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible. This EON device is EOL.
EON	EON	SPI	2.7-3.6	-	32	EN25B32	x1	Split sectors (2x4KB, 1x8KB, 1x16KB, 1x32KB, 63x64KB)	100MHz (@20pF, 3.0-3.6V) 75MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5. This EON device is EOL.
AMIC	EON	SPI	2.7-3.6	-	32	EN25F32	x1	Uniform 4KB /w 64KB Blocks	100MHz (@20pF) 75MHz (@30pF)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5. This EON device is EOL.
Winbond	EON	SPI	2.7-3.6	-	32	EN25Q32A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 100MHz (@20pF) x2, x4: 80MHz (@30pF)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL032P	No	Yes	S25FL032P is pin-compatible with 8-pin SO/16-pin SO and 8-Land SON 6x5. EON device does not have HOLD#. This EON device is EOL.
ESMT	EON	SPI	2.7-3.6	-	32	EN25Q32B	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz (@20pF) x2, x4: 80MHz (@30pF)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 24-Ball BGA 6x8	-40 to +85C	S25FL032P	No	Yes	Package, pinout and core command set compatible. EON device does not have HOLD#.
ESI, Chingis, GigaDevice	EON	SPI	2.7-3.6	-	32	EN25QH32	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz x2, x4: 80MHz x4: 80MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 24-Ball BGA 6x8 8-Pin PDIP 300mil	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible.
Micron, SST, EON, MCP	EON	SPI	2.7-3.6	-	64	EN25B64	x1	Split sectors (2x4KB, 1x8KB, 1x16KB, 1x32KB, 127x64KB)	100MHz (@20pF); 75MHz (@30pF)	16-Pin SO 300mil	-40 to +85C	S25FL064P	Yes	Yes	Package, pinout and core command set compatible. This EON device is EOL.
NAND	EON	SPI	2.7-3.6	-	64	EN25P64	x1	Uniform 64KB	100MHz (@20pF); 75MHz (@30pF)	16-Pin SO 300mil	-40 to +85C	S25FL064P	Yes	Yes	Package, pinout and core command set compatible. This EON device is EOL.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	EON	SPI	2.7-3.6	-	64	EN25QH64	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz; x2: 80MHz; x4: 50MHz	8-Pin SO 208mil; 16-Pin SO 300mil; 8-Land SON 6x5 or 8x6; 8-Pin PDIP 300mil; 24-Ball BGA 6x8	-40 to +85C	S25FL064P	Yes	Yes	FL064P is pin compatible with 16-Pin SO, 8-Land SON 6x8, and 24-Ball BGA 6x8 package
Macronix	EON	SPI	2.7-3.6	-	64	EN25Q64	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz (@20pF); x2, x4: 80MHz (@30pF)	8-Pin SO 208mil; 16-Pin SO 300mil; 8-Land SON 6x5 or 8x6; 8-Pin PDIP 300mil; 24-Ball BGA 6x8	-40 to +85C	S25FL064P	Yes	Yes	Package, pinout and core command set compatible. EON device does not have HOLD#.
Samsung	EON	SPI	2.7-3.6	-	128	EN25Q128	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz (@20pF); x2, x4: 80MHz (@30pF)	16-Pin SO 300mil; 8-Land SON 6x5 or 8x6; 24-Ball BGA 6x8	-40 to +85C	S25FL128S	Yes	Yes	Package, pinout and core command set compatible. EON device does not have HOLD#. Spansion supports 133MHz x1 clock rate, and 104MHz x2, x4 clock rate.
SST	EON	SPI	2.7-3.6	-	128	EN25QH128	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz (@20pF); x2, x4: 80/50MHz (@30pF)	16-Pin SO 300mil; 8-Land SON 6x5 or 8x6; 24-Ball BGA 6x8	-40 to +85C	S25FL128S	Yes	Yes	Package, pinout and core command set compatible. Spansion supports 133MHz x1 clock rate, and 104MHz x2, x4 clock rate.
Atmel	EON	SPI	2.7-3.6	-	256	EN25QH256	x1, x2, x4	Uniform 4KB /w 64KB Blocks	x1: 104MHz (@20pF); x2, x4: 80MHz (@30pF)	16-Pin SO 300mil; 8-Land SON 8x6; 24-Ball BGA 6x8	-40 to +85C	S25FL256S	Yes	Yes	S25FL256S is pin-compatible with 16-pin SO and 8-Land SON 8x6. Spansion supports 133MHz x1 clock rate, and 104MHz x2, x4 clock rate.
EON															
AMIC															
Winbond															
ESMT															
ESI, Chingis, GigaDevice															
Micron, SST, EON, MCP															
NAND															

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	AMIC	ADP	4.5-5.5	-	1	A29010	x8	Uniform Sector	55, 70, 90ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F010B	Yes	Yes	-
Macronix	AMIC	ADP	4.5-5.5	-	1	A29001/ A290011	x8	Boot Sector	55, 70, 90ns	32-Pin PLCC 32-Pin TSOP 32-Pin PDIP	0 to +70C -40 to +85C	Am29F010B	Yes	Yes	-
Samsung	AMIC	ADP	4.5-5.5	-	2	A29002/ A290021	x8	Boot Sector	70, 90, 120, 150ns	32-Pin PDIP 32-Pin PLCC 32-Pin TSOP	0 to +70C	Am29F002B/NB	Yes	Yes	-
	AMIC	ADP	4.5-5.5	-	4	A29040B	x8	Uniform Sector	55, 70ns	32-Pin PDIP 32-Pin PLCC 32-Pin TSOP	0 to +70C -40 to +85C	Am29F040B	Yes	Yes	-
SST	AMIC	ADP	4.5-5.5	-	8	A29800	x8, x16	Boot Sector	55, 70, 90ns	44-Pin SO 48-Pin TSOP	0 to +70C -40 to +85C	Am29F800B	Yes	Yes	-
Atmel	AMIC	ADP	4.5-5.5	-	8	A29801	x8, x16	Boot Sector	55, 70ns	44-Pin SO 48-Pin TSOP 48-Ball TFBGA	0 to +70C -25 to +84C -40 to +85C	Am29F800B	Yes	Yes	-
	AMIC	ADP	2.7-3.6	-	8	A29L800A	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball TFBGA 44-Pin SOP	0 to +70C -25 to +85C -40 to +85C	S29AL008J	Yes	Yes	AMIC device does not have WP#.
EON	AMIC	ADP	2.7-3.6	-	8	A29L008A	x8	Boot Sector	70, 90ns	40-Pin TSOP	0 to +70C -40 to +85C	S29AL008J	No	Yes	-
	AMIC	ADP	2.7-3.6	-	8	A29L008	x8	Boot Sector	70, 90ns	40-Pin TSOP	0 to +70C -40 to +85C	S29AL008J	No	Yes	-
AMIC	AMIC	ADP	4.5-5.5	-	16	A29016	x8	Uniform Sector	55, 70, 90ns	44-Pin SO 40-Pin TSOP 48-Pin TSOP	0 to +70C -40 to +85C	Am29F016D	Yes	Yes	-
Winbond	AMIC	ADP	4.5-5.5	-	16	A29160	x8, x16	Boot Sector	55, 70ns	44-Pin SO 48-Pin TSOP 48-Ball TFBGA	0 to +70C -25 to +84C -40 to +85C	Am29F160D	Yes	Yes	-
	AMIC	ADP	3.0-3.6	-	16	A29L160A	x8, x16	Boot Sector	55, 70ns	48-Pin TSOP 48-Ball FBGA 44-Pin SOP	0 to +70C -25 to +85C -40 to +85C	S29AL016J	Yes	Yes	AMIC device does not have WP#.
ESMT	AMIC	ADP	2.7-3.6 3.0-3.6	-	32	A29L320A	x8, x16	Boot Sector	70, 80, 90, 120ns	48-Pin TSOP 48-Ball TFBGA	0 to +70C -25 to +85C -40 to +85C	S29GL032N	Yes	Yes	This AMIC device only supports full VCC (2.7-3.6) for commercial temperature range. Regulated VCC (3.0-3.6) needed for Industrial & Wireless temperature ranges.
ESI, Chingis, GigaDevice	AMIC	ADP	2.7-3.6	-	64	A29L640	x8, x16	Boot Sector	70ns	44-Pin SOP 48-Pin TSOP 48-Ball TFBGA	0 to +70C -25 to +85C -40 to +85C	S29GL064N	Yes	Yes	S29GL064N is pin-compatible with 48-Pin TSOP and 48-Ball TFBGA.
Micron, SST, EON, MCP	AMIC	SPI	2.7-3.6	-	4	A25L040	x1, x2	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL204K	Yes	Yes	S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
NAND	AMIC	SPI	2.7-3.6	-	8	A25L080	x1, x2	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 150/209mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.

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Micron
Macronix
Samsung
SST
Atmel
EON
AMIC
Winbond
ESMT
ESI, Chingis, GigaDevice
Micron, SST, EON, MCP
NAND

Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
AMIC	SPI	2.7-3.6	-	16	A25L016	x1, x2	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 208mil and 8-Land SON 6x5. S25FL216K is pin-compatible with 8-Pin SO 208mil.
AMIC	SPI	2.7-3.6	-	16	A25LQ16	x1, x2, x4	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 150/209mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO and 8-Land SON 6x5. S25FL216K supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 208mil.
AMIC	SPI	2.7-3.6	-	32	A25L032	x1, x2	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL032P	Yes	Yes	Spansion device supports quad mode and automotive temp range. S25FL032P is pin-compatible with 8-Pin/16-Pin SO and 8-land SON.
AMIC	SPI	2.7-3.6	-	32	A25LQ32A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	100MHz	8-Pin SO 209mil 8-Land SON 6x5 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL032P	Yes	Yes	Spansion device supports automotive temp range. S25FL032P is pin-compatible with 8-Pin/16-Pin SO.
AMIC	SPI	2.7-3.6	-	64	A25LQ064A	x1, x2, x4	Uniform 4KB /w 64KB Blocks	104MHz	8-Pin SO 209mil 16-pin SO 300mil 8-Land SON 6x5 24-ball BGA	-40 to +85C	S25FL064P	Yes	Yes	Spansion device supports automotive temp range. S25FL064P is pin-compatible with 16-Pin SO and BGA.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Winbond	ADP	2.7-3.6	1.65-3.6	32	W29GL032C	x8, x16	Boot Sector Uniform Sector	70ns	56-Pin TSOP 64-Ball LFBGA 48-Pin TSOP 48-Ball TFBGA	-40 to +85	S29GL032N	Yes	Yes	
Macronix	Winbond	ADP	2.7-3.6	1.65-3.6	64	W29GL064C	x8, x16	Boot Sector Uniform Sector	70ns	56-Pin TSOP 64-Ball LFBGA 48-Pin TSOP 48-Ball TFBGA	-40 to +85	S29GL064N	Yes	Yes	
Samsung	Winbond	ADP	2.7-3.6	1.65-3.6	128	W29GL128C	x8, x16	Uniform Sector	90ns	56-PinTSOP 64-Ball LFBGA	-40 to +85	S29GL128S, S29GL128P	Yes	Yes	S29GL128S supports x16-only. S29GL128P supports x8/x16.
SST	Winbond	ADP	2.7-3.6	1.65-3.6	256	W29GL256C	x8, x16	Uniform Sector	90ns	56-PinTSOP 64-Ball LFBGA	-40 to +85	S29GL256S	Yes	Yes	Under Development
SST	Winbond	ADP	2.7-3.6	1.65-3.6	512	W29GL512C	x8, x16	Uniform Sector	90ns	56-PinTSOP 64-Ball LFBGA	-40 to +85	S29GL512S	Yes	Yes	Under Development
Atmel	Winbond	SPI	2.7-3.6	-	4	W25X40AV	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
Atmel	Winbond	SPI	2.3-3.6	-	4	W25X40AL	x1, x2	Uniform 4KB /w 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
EON	Winbond	SPI	2.7-3.6	-	4	W25X40BV	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
AMIC	Winbond	SPI	2.3-3.6	-	4	W25X40BL	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil 8-VSOP 150mil 8-USON 2x3	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
Winbond	Winbond	SPI	2.3-3.6	-	4	W25X40CL	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil 8-VSOP 150mil 8-USON 2x3	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
ESMT	Winbond	SPI	2.6-3.6	-	4	W25X40CV	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-USON 2x3	-40 to +85C -40 to +105C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
ESI, Chingis, GigaDevice	Winbond	SPI	2.3-3.6	-	4	W25Q40BL	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	50MHz	8-Pin SO 150mil/208mil, 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
Micron, SST, EON, MCP	Winbond	SPI	2.3-3.6 2.7-3.6	-	4	W25Q40CL	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil VSOP8 150mil USON8 2X3mm	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
NAND															

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Winbond	SPI	2.7-3.6	-	4	W25Q40BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5	-40 to +85C	S25FL204K	Yes	Yes	Spansion device supports single I/O and dual out. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
Macronix	Winbond	SPI	2.7-3.6	-	8	W25X80AV	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	Spansion device supports single I/O and dual out. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
Samsung	Winbond	SPI	2.3-3.6	-	8	W25X80AL	x1, x2	Uniform 4KB /w 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
SST	Winbond	SPI	2.3-3.6	-	8	W25Q80BL	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	Spansion device supports 2.7-3.6V, single I/O and dual out. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
Atmel	Winbond	SPI	2.7-3.6	-	8	W25Q80BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C -40 to +105C	S25FL208K	Yes	Yes	Spansion device supports single I/O and dual out. S25FL208K is pin-compatible with 8-Pin SO 150mil/208mil.
EON	Winbond	SPI	2.7-3.6	-	16	W25X16AV	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
AMIC	Winbond	SPI	2.3-3.6	-	16	W25X16AL	x1, x2	Uniform 4KB /w 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
Winbond	Winbond	SPI	2.7-3.6	-	16	W25X16BV	x1, x2	Uniform 4KB /w 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is EOL.
ESMT	Winbond	SPI	2.7-3.6	-	16	W25Q16BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. This Winbond device is not recommended for new designs.
ESI, Chingis, GigaDevice	Winbond	SPI	2.3-3.6	-	16	W25Q16CL	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	50MHz	8-Pin SO 150mil/208mil 16-pin SO 300mil 8-Land SON 6x5 8-Pin PDIP 300mil	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil.
Micron, SST, EON, MCP															
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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Winbond	SPI	2.7-3.6	-	16	W25Q16CV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5 24 Ball TFBGA 6X8mm	-40 to +85C -40 to +105C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 24 Ball TFBGA 6X8mm and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil.
Macronix	Winbond	SPI	2.7-3.6	-	16	W25Q16DV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5 24 Ball TFBGA 6X8mm 8-pin VSOP 150/208mil	-40 to +85C -40 to +105C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 24 Ball TFBGA 6X8mm and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil.
Samsung	Winbond	SPI	2.7-3.6	-	16	W25Q16DV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5 24 Ball TFBGA 6X8mm 8-pin VSOP 150/208mil	-40 to +85C -40 to +105C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K is pin-compatible with 8-Pin SO 150mil/208mil, 24 Ball TFBGA 6X8mm and 8-Land SON 6x5. FL216K device supports single I/O and dual out. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil. S25FL216K is pin-compatible with 8-Pin SO 150mil/208mil.
SST	Winbond	SPI	2.7-3.6	-	32	W25X32V	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 8x6	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 8x6. This Winbond device is EOL.
Atmel	Winbond	SPI	2.7-3.6	-	32	W25X32AV	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin SO 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5. This Winbond device is EOL.
EON	Winbond	SPI	2.7-3.6	-	32	W25X32BV	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5. This Winbond device is EOL.
AMIC	Winbond	SPI	2.7-3.6	-	32	W25Q32V	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Land SON 6x5 16-Pin SO 300mil	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible. This Winbond device is EOL.
Winbond	Winbond	SPI	2.7-3.6	-	32	W25Q32BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5 24 Ball TFBGA 6X8mm	-40 to +85C -40 to +105C	S25FL032P	Yes	Yes	S25FL032P is pin-compatible with 8-pin/16-pin SO and 8-Land SON 6x5.
ESMT	Winbond	SPI	2.7-3.6	-	32	W25Q32FV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 208mil 8-Pin VSOP 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5/8x6 24 Ball TFBGA 6X8mm	-40 to +85C -40 to +105C	S25FL032P	Yes	Yes	Core command set compatible. S25FL032P is pin-compatible with 8-pin SO, 8-Land SON 6x5, 8-Land SON 6x8, and 24 Ball TBGA.
ESI, Chingis, GigaDevice	Winbond	SPI	2.7-3.6	-	64	W25X64V	x1, x2	Uniform 4KB /w 64KB Blocks	75MHz	8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO and 8-Land SON 6x8. This Winbond device is EOL.
Micron, SST, EON, MCP	Winbond	SPI	2.7-3.6	-	64	W25X64BV	x1, x2	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO and 8-Land SON 6x8. This Winbond device is EOL.
NAND															

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ESI, Chingis, GigaDevice
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NAND

Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Winbond	SPI	2.7-3.6	-	64	W25Q64BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x8	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO and 8-Land SON 6x8. This Winbond device is EOL.
Winbond	SPI	2.7-3.6	-	64	W25Q64CV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	80MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 or 6x8 8-Pin PDIP 300mil 24 Ball TFBGA 6x8mm	-40 to +85C -40 to +105C	S25FL064P	Yes	Yes	S25FL064P is pin-compatible with 16-pin SO and 8-Land SON 6x8. This Winbond device is not recommended for new designs.
Winbond	SPI	2.7-3.6	-	64	W25Q64FV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 208mil 8-Pin VSOP 208mil 8-Pin PDIP 300mil 16-Pin SO 300mil 8-Land SON 6x5/8x6, 24 Ball TFBGA 6x8mm	-40 to +85C -40 to +105C	S25FL064P	Yes	Yes	Core command set compatible. S25FL032P is pin-compatible with 8-pin/16-pin SO, 8-Land SON 6x8, and 24 Ball TBGA.
Winbond	SPI	2.7-3.6	-	128	W25Q128BV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	x1,x2: 104MHz x4: 70MHz	16-Pin SO 300mil, 8-Land SON 6x8, 24 Ball TFBGA 6x8mm	-40 to +85C -40 to +105C	S25FL128S	Yes	Yes	S25FL128S is pin-compatible with 8-Land SON 6x8. Winbond device does not have #Reset pin and DDR feature. Spansion device has 133Mhz x1 clock frequency. This Winbond device is not recommended for new designs.
Winbond	SPI	2.7-3.6	-	128	W25Q128FV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	8-Pin SO 208mil, 8-Pin VSOP 208mil, 8-Pin PDIP 300mil, 16-Pin SO 300mil, 8-Land SON 6x5 8x6, 24 Ball TFBGA 6x8mm	-40 to +85C -40 to +105C	S25FL128S	Yes	Yes	S25FL128S is pin-compatible with 16-pin SO, 8-Land SON 6x8. Winbond device does not have the DDR feature. Spansion device has 133Mhz x1 clock frequency.
Winbond	SPI	2.7-3.6	-	256	W25Q256FV	x1, x2, x4	Uniform 4KB /w 32KB Blocks & 64KB Blocks	104MHz	16-Pin SO 300mil, 8-Land SON 8x6, 24 Ball TFBGA 6x8mm	-40 to +85C -40 to +105C	S25FL256S	Yes	Yes	S25FL256S is pin-compatible with 16-pin SO, 8-Land SON 6x8. Winbond device does not have the DDR feature. Spansion device has 133Mhz x1 clock frequency.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible*	Notes
Micron	ESMT	ADP	2.7-3.6	2.7-3.6	8	F49L800UA/BA	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP	0 to 70C	S29AL008J	Yes	Yes	ESMT device does not have WP#.
Macronix	ESMT	ADP	2.7-3.6	2.7-3.6	16	F49L160UA/BA	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP	0 to +70C	S29AL016J	Yes	Yes	ESMT device does not have WP#.
	ESMT	ADP	2.7-3.6	2.7-3.6	32	F49L320UA/BA	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP	0 to +70C	S29GL032N	Yes	Yes	
Samsung	ESMT	SPI	2.7-3.6	-	4	F25L004A	x1	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL204K	Yes	Yes	S25FL204K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil/208mil.
	ESMT	SPI	2.7-3.6	-	4	F25L04UA	x1	Split sectors (1x8KB, 2x4KB, 1x16KB, 1x32KB, 7x64KB)	100 MHz (@15pF, 3.2-3.6V) 75 MHz (@15pF, 2.7-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 150mil	0 to +70C	S25FL204K	Yes	Yes	S25FL204K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil.
SST	ESMT	SPI	2.3-3.3	-	4	F25S04PA	x1, x2	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 2.3-3.3V) 86 MHz (@15pF, 2.3-3.3V) 50 MHz (@30pF, 2.3-3.3V)	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil 8-Land SON 6x5	0 to +70C	S25FL204K	Yes	Yes	S25FL204K (2.7-3.6V) supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil/208mil.
Atmel	ESMT	SPI	2.7-3.6	-	8	F25L008A	x1	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	S25FL208K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 208mil.
	ESMT	SPI	2.7-3.6	-	8	F25L08PA	x1, x2	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil	0 to +70C -40 to +85C	S25FL208K	Yes	Yes	S25FL208K supports dual output feature. Spansion device is pin-compatible with 8-Pin SO 150mil/208mil.
EON	ESMT	SPI	2.7-3.6	-	16	F25L016A	x1	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil	0 to +70C -40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports dual and quad I/O feature and is pin-compatible with 8-Pin SO 208mil. S25FL208K supports dual output feature and is pin-compatible with 8-Pin SO 208mil.
AMIC	ESMT	SPI	2.7-3.6	-	16	F25L16PA	x1, x2	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 150mil/208mil 8-Pin PDIP 300mil	0 to +70C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports dual and quad I/O feature and is pin-compatible with 8-Pin SO 150mil/208mil. S25FL208K supports dual output feature and is pin-compatible with 8-Pin SO 150mil/208mil.
Winbond	ESMT	SPI	2.7-3.6	-	16	F25L16QA	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 86 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 150mil/208mil 8-Land SON 6x5 8-Pin PDIP 300mil 16-Pin SO 300mil	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports dual and quad I/O feature and is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. S25FL208K supports dual output feature and is pin-compatible with 8-Pin SO 150mil/208mil.
ESMT	ESMT	SPI	2.7-3.6	-	32	F25L32PA	x1, x2	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 86 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible.
ESI, Chingis, GigaDevice	ESMT	SPI	2.7-3.6	-	32	F25L32QA	x1, x2, x4	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 86 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil	-40 to +85C	S25FL032P	Yes	Yes	Package, pinout and core command set compatible.
	ESMT	SPI	2.7-3.6	-	64	F25L64QA	x1, x2, x4	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 86 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL064P	Yes	Yes	16-pin SO package, pinout and core command set compatible.
Micron, SST, EON, MCP	ESMT	SPI	2.7-3.6	-	128	F25L128QA	x1, x2, x4	Uniform 4KB /w 64KB Blocks	100 MHz (@15pF, 3.0-3.6V) 86 MHz (@15pF, 3.0-3.6V) 50 MHz (@30pF, 2.7-3.6V)	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5	-40 to +85C	S25FL128S	Yes	Yes	16-pin SO package, pinout and core command set compatible; Spansion offers faster read performance.

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	ESI	ADP	2.7-3.6	-	8	ES29LV800E	x8, x16	Boot Sector	70, 90, 120ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29AL008J	Yes	Yes	ESI device does not have WP#.
Macronix	ESI	ADP	2.7-3.6	-	16	ES29LV160E	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	ESI device does not have WP#.
	ESI	ADP	2.7-3.6	-	16	ES29LV160F	x8, x16	Boot Sector	55, 70ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29AL016J	Yes	Yes	ESI device does not have WP#.
Samsung	ESI	ADP	2.7-3.6	-	32	ES29LV320E	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	-
	ESI	ADP	2.7-3.6	-	32	ES29LV320F	x8, x16	Boot Sector	70, 90ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29GL032N	Yes	Yes	-
SST	ESI	ADP	2.7-3.6 3.0-3.6	-	64	ES29LV640	x8, x16	Boot Sector	55, 70ns	48-Pin TSOP 48-Ball FBGA	0 to +70C -40 to +85C	S29GL064N	Yes	Yes	55ns access time only available for 3.0-3.6 voltage range.
	Chingis ISSI	SPI	2.3 - 3.6	-	4	IS25LD040	x1, x2	Uniform 4KB /w 64KB blocks	33M/104MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil 8-Land SON 6x5	-40 to +105C	S25FL204K	Yes	No	Spansion FL204K is 2.7V-3.6V Vcc. S25FL204K is pin-compatible with 8-Pin SO 150mil/208mil.
Atmel	Chingis ISSI	SPI	2.3 - 3.6	-	4	IS25LQ040	x1, x2, x4	Uniform 4KB /w 64KB blocks	33M/104MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil 8-Land SON 6x5 8-Land SON 2x3	-40 to +125C	S25FL204K	Yes	Yes	Spansion FL204K is 2.7V-3.6V Vcc. S25FL204K supports dual output feature and is pin-compatible with 8-Pin SO 150mil/208mil.
EON	Chingis ISSI	SPI	2.3 - 3.6	-	8	IS25LQ080	x1, x2, x4	Uniform 4KB /w 64KB blocks	33M/104MHz	8-Pin SO 208mil 8-pin PDIP 300mil 8-Land SON 6x5	-40 to +125C	S25FL208K	Yes	Yes	Spansion FL208K is 2.7V-3.6V Vcc. S25FL208K supports dual output feature and is pin-compatible with 8-Pin SO 150mil/208mil.
AMIC	Chingis ISSI	SPI	2.3 - 3.6	-	16	IS25LQ016	x1, x2, x4	Uniform 4KB /w 64KB blocks	33M/104MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil 8-Land SON 6x5	-40 to +125C	S25FL116K / S25FL216K	Yes	Yes	S25FL116K supports dual and quad I/O feature and is pin-compatible with 8-Pin SO 150mil/208mil and 8-Land SON 6x5. S25FL208K supports dual output feature and is pin-compatible with 8-Pin SO 150mil/208mil.
Winbond	Chingis ISSI	SPI	2.7 - 3.6	-	32	IS25CQ032	x1, x2, x4	Uniform 4KB /w 64KB blocks	33M/104MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-pin PDIP 300mil 8-Land SON 6x5	-40 to +125C	S25FL032P	Yes	Yes	S25FL032P is support automotive grade at +105C. Spansion device supports 8-Pin SO 208mil, 16-Pin SO 300mil and 8-Land SON 6x5.
ESMT	GigaDevice	SPI	2.7-3.6	-	4	GD25Q40	x1, x2, x4	Uniform 4KB/w 32/64KB Blocks	120MHz	8-Pin SO 150mil/208mil 8-Land SON 6x5/3x2	-40 to +85C	S25FL204K	Yes	Yes	S25FL204K has dual output.
ESI, Chingis, GigaDevice	GigaDevice	SPI	2.7-3.6	-	8	GD25Q80	x1, x2, x4	Uniform 4KB/w 32/64/128KB Blocks	120MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K has dual output.
	GigaDevice	SPI	2.7-3.6	-	8	GD25Q80B	x1, x2, x4	Uniform 4KB/w 32/64KB Blocks	120MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil	-40 to +85C	S25FL208K	Yes	Yes	S25FL208K has dual output.
Micron, SST, EON, MCP	GigaDevice	SPI	2.7-3.6	-	16	GD25Q16	x1, x2, x4	Uniform 4KB/w 32/64/128KB Blocks	120MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil	-40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad I/O and is pin-compatible with 8-Pin SO 208mil. S25FL216K supports dual output and is pin-compatible with 8-Pin SO 208mil.
NAND															

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	Manufacturer	Interface	Voltage (V)	VIO (V)	Density (Mb)	Device	Bus Width	Sector Type/ Bank(s)	Initial Access Times/ Clock Frequency	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	GigaDevice	SPI	2.7-3.6	-	16	GD25Q16B	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	120MHz	8-Pin SO 150mil/208mil 8-pin PDIP 300mil	0 to +70C -40 to +85C	S25FL116K/ S25FL216K	Yes	Yes	S25FL116K supports quad I/O and is pin-compatible with 8-Pin SO 208mil. S25FL216K supports dual output and is pin-compatible with 8-Pin SO 208mil.
Macronix	GigaDevice	SPI	2.7-3.6	-	32	GD25Q32	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	120MHz	8-Pin SO 208mil, 8-Land SON 6x5 8-pin PDIP 300mil	0 to +70C -40 to +85C	S25FL032P	Yes	Yes	S25FL032P supports automotive temperature range. S25FL032P is pin-compatible with 8-Pin SO 208mil and 8-USON 5x6.
Samsung	GigaDevice	SPI	2.7-3.6	-	32	GD25Q32B	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	120MHz	8-Pin SO 208mil 8-Land SON 6x5 8-pin PDIP 300mil 24-Ball BGA 6x8	0 to +70C -40 to +85C	S25FL032P	Yes	Yes	S25FL032P supports automotive temperature range. S25FL032P is pin-compatible with 8-Pin SO 208mil, 8-USON 5x6, and BGA 6x8.
SST	GigaDevice	SPI	2.7-3.7	-	64	GD25Q64B	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	120MHz	8-Pin SO 208mil 16-Pin SO 300mil 8-Land SON 6x5 8-pin PDIP 300mil 24-Ball BGA 6x8	-40 to +85C	S25FL064P	Yes	Yes	S25FL064P supports automotive temperature range. S25FL064P is pin-compatible with 16-Pin SO 300mil, and BGA 6x8.
Atmel	GigaDevice	SPI	2.7-3.8	-	128	GD25Q128B	x1, x2, x4	Uniform 4KB /w 32/64KB Blocks	104MHz	8-Land SON 6x8 16-pin SO 300mil	0 to +70C -40 to +85C	S25FL128S	Yes	Yes	Pin-compatible with 16-Pin SO and 8-SON. Spansion device has 133MHz x1 clock frequency, DDR feature and automotive temp range support.
EON															
AMIC															
Winbond															
ESMT															
ESI, Chingis, GigaDevice															
Micron, SST, EON, MCP															
NAND															

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Device	NOR	pSRAM	DRAM	NAND	Sector	VCC (V)	VIO (V)	Bus Type	Bus Width	Packages	Recommended Spansion OPN	Notes
Micron	Micron	PF38F6070MQ0C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/11x11mm	S71WS-P	Contact factory for best replacement option.
	Micron	PF38F6070MQ1C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/11x11mm	S71NS-P	Contact factory for best replacement option.
Macronix	Micron	PF38F6070MOY0C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/11x11mm	S71WS-P	Contact factory for best replacement option.
	Micron	JZ58F0049MQ0G	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	128-ball PoP/12x12mm	S71WS-P	Contact factory for best replacement option.
	Micron	PF58F0064MOY0W	1Gb	-	1Gb SDR	-	Uniform	1.8	1.8	ADP	x32	165-ball/11x13mm	S72WS-P	Contact factory for best replacement option.
	Micron	PF58F0083MQ0V	1Gb	-	1Gb SDR	2Gb	Uniform	1.8	1.8	ADP	x16	165-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
Samsung	Micron	PF58F0051MOY0W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADP	x16	165-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
	Micron	PF58F0051MOY1W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS-P	Contact factory for best replacement option.
	Micron	PF58F0051MQ01W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS-P	Contact factory for best replacement option.
SST	Micron	PF38F6070MOY0B	1Gb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
	Micron	PF38F6070MOY0V	1Gb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	165-ball/10x11mm	S72WS-P	Contact factory for best replacement option.
	Micron	PF58F0033MOY0B	1Gb	-	-	2Gb	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	WS-P	Contact factory for best replacement option.
Atmel	Micron	PF58F0033MOY1B	1Gb	-	-	2Gb	Uniform	1.8	1.8	ADM	x16	105-ball/9x11mm	NS-P	Contact factory for best replacement option.
	Micron	PF58F0062MOY1B	1Gb	-	-	2x2Gb	Uniform	1.8	1.8	ADM	x16	105-ball/9x11mm	NS-P	Contact factory for best replacement option.
	Micron	PF58F0080MOY1B	1Gb	-	-	4Gb	Uniform	1.8	1.8	ADM	x16	105-ball/11x13mm	NS-P	Contact factory for best replacement option.
EON	Micron	PF38F5070MOY0C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/9x11mm	S71WS-P	Contact factory for best replacement option.
	Micron	PF38F5070MOY3C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/9x11mm	S71NS-P	Contact factory for best replacement option.
	Micron	PF38F5070MQ3C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/9x11mm	S71NS-P	Contact factory for best replacement option.
	Micron	PF38F5070MOY3D	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/8x11mm	S71NS-P	Contact factory for best replacement option.
AMIC	Micron	JZ58F0101MOY0G	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	104-ball PoP/10x10mm	S71WS-P	Contact factory for best replacement option.
	Micron	PF38F5066MOY3D	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/10x10mm	S71NS-P	Contact factory for best replacement option.
	Micron	PF38F5066MOY0C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/10x10mm	S71WS-P	Contact factory for best replacement option.
Winbond	Micron	PF38F5060MOY0C	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x11mm	S71WS512PDO	Contact factory for best replacement option.
	Micron	PF38F5060MOY3C	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/8x11mm	S71NS512PDO	Contact factory for best replacement option.
	Micron	PF38F5060MOY3D	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/8x11 or 8x8mm	S71NS512PDO	Contact factory for best replacement option.
	Micron	PF38F5060MOY0Y	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADP	x16	84-ball/8x10mm	S71WS512PDO	Contact factory for best replacement option.
ESMT	Micron	PF38F5060MOY1Y	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	84-ball/8x10mm	S71NS512PDO	Contact factory for best replacement option.
	Micron	JZ58F0085MOY0G	512Mb	128Mb	-	-	Uniform	1.8	1.8	ADP	x16	104-ball PoP/10x10mm	S71WS512PDO	Contact factory for best replacement option.
	Micron	PF38F5050MOY0C	512Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x11mm	S71WS512PCO	Contact factory for best replacement option.
	Micron	PF58F0075MOY1W	512Mb	-	512Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS-P	Contact factory for best replacement option.
ESI, Chingis, GigaDevice	Micron	PF38F5070MOY0B	512Mb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS512PE0	Contact factory for best replacement option.
	Micron	PF38F5070MOY1E	512Mb	-	256Mb DDR	-	Uniform	1.8	1.8	ADM	x16	133-ball/8x8mm	S72NS512RE0	Contact factory for best replacement option.
	Micron	PF38F5070MOY1V	512Mb	-	256Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS512RE0	Contact factory for best replacement option.
Micron, SST, EON, MCP	Micron	PF58F0058MOY1W	512Mb	-	256Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS512RE0	Contact factory for best replacement option.
	Micron	PF38F5060MOY0B	512Mb	-	128Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
	Micron	PF38F5060MOY1E	512Mb	-	128Mb DDR	-	Uniform	1.8	1.8	ADM	x16	133-ball/8x8mm	S72NS512RDO	Contact factory for best replacement option.
	Micron	PF58F0065MOY1W	512Mb	-	128Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS512RDO	Contact factory for best replacement option.
NAND	Micron	PF38F4060MOY3C	256Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/8x10mm	S71VS256RDO	Contact factory for best replacement option.
	Micron	PF38F4060MOY0C	256Mb	128Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x10mm	S71VS256PDO	Contact factory for best replacement option.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed.

	Manufacturer	Device	NOR	pSRAM	DRAM	NAND	Sector	VCC (V)	VIO (V)	Bus Type	Bus Width	Packages	Recommended Spansion OPN	Notes
Micron	Micron	PF38F4060MOY0Y	256Mb	128Mb	-	-	Uniform	1.8	1.8	ADP	x16	84-ball/8x10mm	S71WS256PDO	Contact factory for best replacement option.
	Micron	PF38F4060MOY1Y	256Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	84-ball/8x10mm	S71WS256RDO	Contact factory for best replacement option.
Macronix	Micron	PF38F4060MOY3D	256Mb	128Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/8x8mm	S71WS256RDO	Contact factory for best replacement option.
	Micron	PF38F4050MOY0C	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	PF38F4050MOY3C	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/8x10mm	S71WS256RCO	Contact factory for best replacement option.
Samsung	Micron	PF38F4050MOY0Y	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	84-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	PF38F4050MOY1Y	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	84-ball/8x10mm	S71WS256RDO	Contact factory for best replacement option.
	Micron	PF38F4050MOY3D	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/8x8 or 7.7x6.2mm	S71WS256RDO	Contact factory for best replacement option.
	Micron	PF38F4050MOY0Q	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
SST	Micron	PF38F4050MOY1Q	256Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	88-ball/8x10mm	S71WS256RDO	Contact factory for best replacement option.
	Micron	JZ58F0084MOY1G	256Mb	-	256Mb DDR	-	Uniform	1.8	1.8	ADM	x16	128-ball PoP/12x12mm	S72VS256REO	Contact factory for best replacement option.
	Micron	PF38F4060MOY0B	256Mb	-	128Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72VS256REO	Contact factory for best replacement option.
Atmel	Micron	PF58F0097MOY1B	256Mb	-	-	4Gb	Uniform	1.8	1.8	ADM	x16	105-ball/11x13mm	NS-P	Contact factory for best replacement option.
	Micron	PF38F3050MOY0C	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x10mm	S71WS128PCO	Contact factory for best replacement option.
	Micron	PF38F3050MOY0Y	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	84-ball/8x10mm	S71WS128PCO	Contact factory for best replacement option.
	Micron	PF38F3050MOY1Y	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	84-ball/8x10mm	S71WS128RCO	Contact factory for best replacement option.
EON	Micron	PF38F3050MOY3D	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/6.2x7.7mm	S71WS128RCO	Contact factory for best replacement option.
	Micron	PF38F3050MOY3Q	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADM	x16	88-ball/8x10mm	S71WS128RCO	Contact factory for best replacement option.
	Micron	PF38F3050MOY0Q	128Mb	64Mb	-	-	Uniform	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS128PCO	Contact factory for best replacement option.
AMIC	Micron	PF38F3040MOY0C	128Mb	32Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	PF38F3040MOY3D	128Mb	32Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/6.2x7.7mm	S71WS128RB0	Contact factory for best replacement option.
	Micron	PF38F3040MOY3Q	128Mb	32Mb	-	-	Uniform	1.8	1.8	ADM	x16	88-ball/8x10mm	S71WS128RB0	Contact factory for best replacement option.
	Micron	PF38F3040MOY0Q	128Mb	32Mb	-	-	Uniform	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
Winbond	Micron	PF38F3060MOY1E	128Mb	-	128Mb DDR	-	Uniform	1.8	1.8	ADM	x16	133-ball/8x8mm	S72VS256REO	Contact factory for best replacement option.
	Micron	PF58F0079LLY0W	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	165-ball/9x11mm	S71WS-P	Contact factory for best replacement option.
	Micron	M39LNR9A90E3P5HF	512Mb	-	512Mb DDR	-	Uniform	1.8	1.8	ADP	x16	160-ball PoP/15x15mm	S72WS-P	Contact factory for best replacement option.
ESMT	Micron	PF38F5070LOYB	512Mb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS512PE0	Contact factory for best replacement option.
	Micron	JZ58F0046LOYGG	512Mb	-	256Mb DDR	-	Uniform	1.8	1.8	ADM	x16	128-ball PoP/12x12mm	S72NS512RE0	Contact factory for best replacement option.
	Micron	PF38F4470LLYBBE	2 x 256Mb	-	256Mb SDR	-	Boot	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS512PE0	Contact factory for best replacement option.
	Micron	PF38F4460LLYBBE	2 x 256Mb	-	128Mb SDR	-	Boot	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
ESI, Chingis, GigaDevice	Micron	PF38F4050LOYQE	256Mb	64Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71WS256RCO	Contact factory for best replacement option.
	Micron	M36LOR8060L/U3ZAM	256Mb	64Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71WS256RCO	Contact factory for best replacement option.
	Micron	M36LOR8060B/T9ZAQ	256Mb	64Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	M36LOT8060B/T3ZAQ	256Mb	64Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
Micron, SST, EON, MCP	Micron	M36LOT8060B/T3ZSP	256Mb	64Mb	-	-	Boot	1.8	3	ADP	x16	80-ball/7.7x9mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	PF38F4040LOYWAE	256Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	44-ball/7.7x6.2mm	S71WS256RCO	Contact factory for best replacement option.
	Micron	PF38F4040LOYWAF	256Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	44-ball/7.7x6.2mm	S71WS256RCO	Contact factory for best replacement option.
	Micron	PF38F4040LOYWAG	256Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	44-ball/7.7x6.2mm	S71WS256RCO	Contact factory for best replacement option.
NAND	Micron	M36LOR8050L/U2ZB	256Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	44-ball/7.7x9mm	S71WS256RCO	Contact factory for best replacement option.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed.

	Manufacturer	Device	NOR	pSRAM	DRAM	NAND	Sector	VCC (V)	VIO (V)	Bus Type	Bus Width	Packages	Recommended Spansion OPN	Notes
Micron	Micron	PF38F4060L0Y1EE	256Mb	-	128Mb DDR	-	Boot	1.8	1.8	ADP	x16	133-ball/8x8mm	S72WS256PDO	Contact factory for best replacement option.
Macronix	Micron	M39L0R8070B1P5HF	256Mb	-	128Mb DDR	-	Boot	1.8	1.8	ADP	x16	160-ball PoP/15x15mm	S72WS256PDO	Contact factory for best replacement option.
	Micron	M36L0R7060L/U3ZS	128Mb	64Mb	-	-	Boot	1.8	1.8	ADM	x16	56-ball/8x6mm	S71VS128RCO	Contact factory for best replacement option.
	Micron	M36L0R7060U3ZAM	128Mb	64Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71VS128RCO	Contact factory for best replacement option.
	Micron	M36L0R7060B/T2ZAQ	128Mb	64Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS128PCO	Contact factory for best replacement option.
Samsung	Micron	M36L0T7060B/T3ZAQ	128Mb	64Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S71WS128PCO	Contact factory for best replacement option.
	Micron	M36L0T7060B/T3ZSP	128Mb	64Mb	-	-	Boot	1.8	3	ADP	x16	80-ball/7.7x9mm	S71WS128PCO	Contact factory for best replacement option.
	Micron	M36L0R7050B/T3ZAQ	128Mb	32Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	M36L0R7050B/T4ZAQ	128Mb	32Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
SST	Micron	M36L0R7050L/U3ZAM	128Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71VS128RBO	Contact factory for best replacement option.
	Micron	M36L0R7050L/U3ZS	128Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	56-ball/8x6mm	S71VS128RBO	Contact factory for best replacement option.
	Micron	M36L0T7050B/T3ZAQ	128Mb	32Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
Atmel	Micron	M36L0T7050B/T4ZAQ	128Mb	32Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	M36L0T7050B/T3ZSP	128Mb	32Mb	-	-	Boot	1.8	3	ADP	x16	80-ball/7.7x9mm	S71WS256PCO	Contact factory for best replacement option.
	Micron	M36L0R7040U3ZA	128Mb	16Mb	-	-	Boot	1.8	1.8	ADM	x16	40-ball/7.5x5mm	S71NS-P/S71VS-R	Contact factory for best replacement option.
	Micron	M39L0R7070U3ZE	128Mb	-	128Mb DDR	-	Boot	1.8	1.8	ADM	x16	133-ball/8x8mm	S72VS256RE0	Contact factory for best replacement option.
EON	Micron	M39L0R7070U3P2W	128Mb	-	128Mb DDR	-	Boot	1.8	1.8	ADM	x16	128-ball PoP/12x12mm	S72VS256RE0	Contact factory for best replacement option.
	Micron	M36W0R6050U/L4ZAM	64Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71VS064RBO	Contact factory for best replacement option.
	Micron	M36W0R6050U/L4ZS	64Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	56-ball/8x6mm	S71VS064RBO	Contact factory for best replacement option.
AMIC	Micron	M36W0R6050U/L5ZS	64Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	56-ball/8x6mm	S71VS064RBO	Contact factory for best replacement option.
	Micron	M36W0R6050U/L5ZAM	64Mb	32Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S71VS064RBO	Contact factory for best replacement option.
	Micron	M36W0R6050B/T4ZAQ	64Mb	32Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RBO	Contact factory for best replacement option.
	Micron	M36W0T6050T/B3ZAE	64Mb	32Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RBO	Contact factory for best replacement option.
Winbond	Micron	M36W0T6040T/B3ZAE	64Mb	16Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R6040B/T4ZAQ	64Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R6040B/T7ZAQ	64Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R6040U/L4ZAM	64Mb	16Mb	-	-	Boot	1.8	1.8	ADM	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
ESMT	Micron	M36W0R6040U/L4ZS	64Mb	16Mb	-	-	Boot	1.8	1.8	ADM	x16	56-ball/8x6mm	S71VS064RBO	Contact factory for best replacement option.
	Micron	M36W0R6040U/L6ZS	64Mb	16Mb	-	-	Boot	1.8	1.8	ADM	x16	52-ball/6x4mm	S71VS064RBO	Contact factory for best replacement option.
	Micron	M36W0R6040B/T8ZAQ	64Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
ESI, Chingis, GigaDevice	Micron	M36W0R5040B/T4ZAQ	32Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R5040B/T7ZAQ	32Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R5040B/T8ZAQ	32Mb	16Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
Micron, SST, EON, MCP	Micron	M36W0T5040T/B1ZAQ	32Mb	16Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0T5040B0ZAZ	32Mb	16Mb	-	-	Boot	1.8	3	ADP	x16	88-ball/8x10mm	S98WS064RA0	Contact factory for best replacement option.
	Micron	M36W0R5030B/T7ZAQ	32Mb	8Mb	-	-	Boot	1.8	1.8	ADP	x16	88-ball/8x10mm	S71VS-R	Contact factory for best replacement option.
	Micron	M36W0R5030U/L5ZS	32Mb	8Mb	-	-	Boot	1.8	1.8	ADM	x16	52-ball/6x4mm	S71VS-R	Contact factory for best replacement option.
NAND	Micron	M36W0R5030U3ZS	32Mb	8Mb	-	-	Boot	1.8	1.8	ADM	x16	52-ball/6x4mm	S71VS-R	Contact factory for best replacement option.
	Micron	M36A0W6050B/TOZSP	64Mb	32Mb	-	-	Boot	3	3	ADP	x16	80-ball/7x9mm	S98GL064NBO	Contact factory for best replacement option.

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed.

	Manufacturer	Device	NOR	pSRAM	DRAM	NAND	Sector	VCC (V)	VIO (V)	Bus Type	Bus Width	Packages	Recommended Spansion OPN	Notes
Micron	Micron	M36A0W6040B/TOZSP	64Mb	16Mb	-	-	Boot	3	3	ADP	x16	80-ball/7x9mm	S98GL064NBO	Contact factory for best replacement option.
Macronix	Micron	M36A0W5040B/TI2AI	32Mb	16Mb	-	-	Boot	3	3	ADP	x16	8x12mm	S71GL032NAO	Contact factory for best replacement option.
	Micron	M36A0W5040B/TOZSP	32Mb	16Mb	-	-	Boot	3	3	ADP	x16	80-ball/7x9mm	S71GL032NAO	Contact factory for best replacement option.
	Micron	M36A0W5030B/TOZSP	32Mb	8Mb	-	-	Boot	3	3	ADP	x16	80-ball/7x9mm	S71GL032NAO	Contact factory for best replacement option.
Samsung	SST	PF38F6070M0Q0C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/11x11mm	S71WS-P	Contact factory for best replacement option.
	SST	PF38F6070M0Q1C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/11x11mm	S71NS-P	Contact factory for best replacement option.
	SST	PF38F6070M0Y0C	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/11x11mm	S71WS-P	Contact factory for best replacement option.
	SST	JZ58F0049M0Q0G	1Gb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	128-ball PoP/12x12mm	S71WS-P	Contact factory for best replacement option.
SST	SST	PF58F0064M0Y0W	1Gb	-	1Gb SDR	-	Uniform	1.8	1.8	ADP	x32	165-ball/11x13mm	S72WS-P	Contact factory for best replacement option.
	SST	PF58F0083M0Q0V	1Gb	-	1Gb SDR	2Gb	Uniform	1.8	1.8	ADP	x16	165-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
	SST	PF58F0051M0Y0W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADP	x16	165-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
Atmel	SST	PF58F0051M0Y1W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS-P	Contact factory for best replacement option.
	SST	PF58F0051M0Q1W	1Gb	-	512Mb DDR	-	Uniform	1.8	1.8	ADM	x16	165-ball/9x11mm	S72NS-P	Contact factory for best replacement option.
	SST	PF38F6070M0Y0B	1Gb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	S72WS-P	Contact factory for best replacement option.
EON	SST	PF38F6070M0Y0V	1Gb	-	256Mb SDR	-	Uniform	1.8	1.8	ADP	x16	165-ball/10x11mm	S72WS-P	Contact factory for best replacement option.
	SST	PF58F0033M0Y0B	1Gb	-	-	2Gb	Uniform	1.8	1.8	ADP	x16	105-ball/9x11mm	WS-P	Contact factory for best replacement option.
	SST	PF58F0033M0Y1B	1Gb	-	-	2Gb	Uniform	1.8	1.8	ADM	x16	105-ball/9x11mm	NS-P	Contact factory for best replacement option.
	SST	PF58F0062M0Y1B	1Gb	-	-	2x2Gb	Uniform	1.8	1.8	ADM	x16	105-ball/9x11mm	NS-P	Contact factory for best replacement option.
AMIC	SST	PF58F0080M0Y1B	1Gb	-	-	4Gb	Uniform	1.8	1.8	ADM	x16	105-ball/11x13mm	NS-P	Contact factory for best replacement option.
	SST	PF38F5070M0Y0C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	107-ball/9x11mm	S71WS-P	Contact factory for best replacement option.
	SST	PF38F5070M0Y3C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/9x11mm	S71NS-P	Contact factory for best replacement option.
Winbond	SST	PF38F5070M0Q3C	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	107-ball/9x11mm	S71NS-P	Contact factory for best replacement option.
	SST	PF38F5070M0Y3D	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADM	x16	56-ball/8x11mm	S71NS-P	Contact factory for best replacement option.
	SST	JZ58F0101M0Y0G	512Mb	256Mb	-	-	Uniform	1.8	1.8	ADP	x16	104-ball PoP/10x10mm	S71WS-P	Contact factory for best replacement option.
ESMT	SST	SST34HF32A4	32Mb	16Mb	-	-	Boot	2.7-3.3	2.7-3.3	ADP	x8, x16	56-ball/8x10mm 62-ball/8x10mm	S71GL032NAO	S71GL032NAO is pin-compatible with the 56-ball MCP. SST device is a dual-bank device.
	EON	EN71GL064B0	64Mb	32Mb	-	-	Boot	2.7-3.3	2.7-3.3	ADP	x16	56-ball/7x9mm	S71GL064NBO	-
	EON	EN71NS064B0	64Mb	32Mb	-	-	Boot	1.7-1.95	1.7-1.95	ADM	x16	56-ball/6.2x7.7mm	S71VS064RBO	S71VS064R does not have WP#.
	EON	EN71NS128B0	128Mb	32Mb	-	-	Boot	1.7-1.95	1.7-1.95	ADM	x16	56-ball/6.2x7.7mm	S71VS128RBO	S71VS128R uses a simplified command set and does not have WP#.
ESI, Chingis, GigaDevice	EON	EN71NS128C0	128Mb	64Mb	-	-	Boot	1.7-1.95	1.7-1.95	ADM	x16	56-ball/6.2x7.7mm	S71VS128RC0	S71VS128R uses a simplified command set and does not have WP#.
Micron, SST, EON, MCP														
NAND														

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed.

	Manufacturer	Voltage (V)	Density (Gb)	Device	I/O Bus Width	Number of Blokcs	Page size (Bytes)	Sequential Acces Time (ns)	Random Access Time (uS)	Page Program Time (uS)	Block Erase Time (mS)	Packages	Temp Range	Recommended Spansion OPN	Pin Com-patible	Command Com-patible	Notes
Micron	Hynix	2.7-3.6	1	HY27FUF081G2A	x8	1024	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm USOP 12x17x0.65mm VFBGA 63-ball 9x11x1mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Spansion 1G part doesn't support copyback commands. Seq. Access 25ns, Random 30uS, Program 200uS, Erase 2ms.
Macronix	Hynix	2.7-3.6	1	H27U1G8	x8	1024	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Spansion1G part doesn't support copyback commands. Seq. Access 25ns, Random 25uS, Program 200uS, Erase 3ms.
Samsung	Hynix	2.7-3.6	2	HY27FUF082G	x8	2048	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm ULGA 52-ball 12x17x0.65mm	-40 to +85C	S34ML02G1	Yes	Yes	Seq. Access 25ns, Random 25uS, Program 200uS, Erase 2ms.
SST	Hynix	2.7-3.6	4	HY27UG084G	x8	4096	2048+64	50	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm ULGA 52-ball 12x17x0.65mm	-40 to +85C	S34ML04G1/ S34ML04G2	Yes	Yes	Seq. Access 50ns, Random 30uS, Program 200uS, Erase 2ms.
Atmel	Hynix	1.7-1.95	1	H27S1G8F2B	x8	1024	2048+64	45	25	250	3.5	FBGA 63-ball 9x11x1mm	-40 to +85C	S34MS01G1	Yes	Yes	1.8V, x8 1Gb.
EON	Hynix	1.7-1.95	1	H27S1G6F2B	x16	1024	1024+ 32 words	45	25	250	3.5	FBGA 63-ball 9x11x1mm	-40 to +85C	S34MS01G1	Yes	Yes	1.8V x16 1Gb.
	Hynix	1.7-1.95	2	H27S2G6F2B	x16	2048	1024+ 32 words	45	25	250	3.5	FBGA 63-ball 9x11x1mm	-40 to +85C	S34MS01G1	Yes	Yes	1.8V x16 2Gb.
AMIC	Hynix	2.7-3.6	2	H27U2G6F2B	x16	2048	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	VFBGA 63-ball 9x11x1mm	-40 to +85C	S34ML02G1	Yes	Yes	Seq. Access 25ns, Random 25 uS, Program 200uS, Erase 2ms.
Winbond	Micron	2.7-3.6	1	MT29F1G08A	x8	1024	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Spansion 1G part doesn't support copyback commands. Seq. Access 25/45ns, Random 25uS, Program 200uS, Erase 2/3.5ms.
	Numonyx (Micron)	2.7-3.6	1	NAND01GW3B	x8	1024	2048+64	50	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm TFBGA 63-ball 9.5X11X1.2mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Seq. Access 50ns, Random 25uS, Program 300uS, Erase 2ms.
ESMT	Numonyx (Micron)	2.7-3.6	1	NAND01GR3B	x8	1024	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm TFBGA 63-ball 9.5X11X1.2mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Seq. Access 50ns, Random 25uS, Program 300uS, Erase 2ms.
ESI, Chingis, GigaDevice	Micron	2.7-3.6	2	MT29F2G08A	x8	2048	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm	-40 to +85C	S34ML02G1	Yes	Yes	Seq. Access 20/25ns, Random 25uS, Program 200uS, Erase 700uS.
Micron, SST, EON, MCP	Micron	2.7-3.6	4	MT29F4G08A	x8	4096	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFBGA 63-ball 9x11x1mm	-40 to +85C	S34ML04G1/ S34ML04G2	Yes	Yes	Seq. Access 20/25ns, Random 25uS, Program 200uS, Erase 700uS.
NAND																	

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.

	Manufacturer	Voltage (V)	Density (Gb)	Device	I/O Bus Width	Number of Blocks	Page size (Bytes)	Sequential Access Time (ns)	Random Access Time (uS)	Page Program Time (uS)	Block Erase Time (mS)	Packages	Temp Range	Recommended Spansion OPN	Pin Compatible	Command Compatible	Notes
Micron	Micron	2.7-3.6	8	MT29F8G08A	x8	8112	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFPGA 63-ball 9x11x1mm	-40 to +85C	S34ML08G1	Yes	Yes	TSOP - Two Chip Enables, BGA - Single Chip Enable.
Macronix	Micron	1.7-1.95	1	MT29F1G08A	x8	1024	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	VFPGA 63-ball 9x11x1mm	-40 to +85C	S34ML01G1	Yes	Yes	1.8V, x8 1Gb.
Samsung	Micron	1.7-1.95	1	MT29F1G16A	x16	1024	1024+32 words	20 to 30	25 to 35	200 to 300	2 to 3	VFPGA 63-ball 9x11x1mm	-40 to +85C	S34ML01G1	Yes	Yes	1.8V x16 1Gb.
	Micron	1.7-1.95	2	MT29F2G16A	x16	2048	1024+32 words	45	25	250	3.5	FBGA 63-ball 9x11x1mm	-40 to +85C	S34MS01G1	Yes	Yes	1.8V x16 2Gb.
SST	Micron	2.7-3.6	2	MT29F8G16A	x16	2048	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	VFPGA 63-ball 9x11x1mm	-40 to +85C	S34ML02G1	Yes	Yes	Seq. Access 25ns, Random 25uS, Program 200uS, Erase 2ms.
	Samsung	2.7-3.6	1	K9F1G08U0D	x8	1024	2048+64	20 to 30	40	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm FBGA 63-ball 9x11x0.8mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Spansion 1G part doesn't support copyback commands. Seq. Access 25/45ns, Random 25uS, Program 200uS, Erase 2/3.5ms.
Atmel	Samsung	2.7-3.6	2	K9F2G08U0D	x8	2048	2048+64	20 to 30	40	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm FBGA 63-ball 9x11x0.8mm	-40 to +85C	S34ML02G1/ S34ML02G2	Yes	Yes	Seq. Access 20/25ns, Random 25uS, Program 200uS, Erase 700uS.
EON	Samsung	2.7-3.6	4	K9F4G08U0D	x8	4096	2048+64	20 to 30	40	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm FBGA 63-ball 9x11x0.8mm	-40 to +85C	S34ML04G1/ S34ML04G2	Yes	Yes	Seq. Access 20/25ns, Random 25uS, Program 200uS, Erase 700uS.
AMIC	Samsung	2.7-3.6	8	K9F8G08U0D	x8	8112	2048+64	20 to 30	40	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm FBGA 63-ball 9x11x0.8mm	-40 to +85C	S34ML08G1/ S34ML04G2	Yes	Yes	TSOP - Two Chip Enables, BGA - Single Chip Enable
Winbond	Toshiba	2.7-3.6	2	TC58NVG1S3	x8	2048	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	TSOP 48-pin 12x20x1.2mm VFPGA 63-ball 9x11x1 mm	-40 to +85C	S34ML01G1/ S34ML01G2	Yes	Yes	Spansion 1G part doesn't support copyback commands. Seq. Access 25/45ns, Random 25uS, Program 200uS, Erase 2.5ms.
ESMT	Toshiba	2.7-3.6	4	TC58NVG2S3	x8	4096	2048+64	20 to 30	25 to 35	200 to 300	2 to 3	P-TFBGA63-1013-0.80AZ	-40 to +85C	S34ML04G1/ S34ML04G2	No	Yes	TC58NVG2S3EBA15 not available in TSOP. Seq. Access 25ns, Random 30uS, Program 300uS, Erase 2.5ms.
ESI, Chingis, GigaDevice																	
Micron, SST, EON, MCP																	
NAND																	

Bus Types - ADP: Address Data Parallel, ADM: Address Data Multiplexed, AADM: Address-High, Address-Low, Data Multiplexed. * Core command set compatible.



ABOUT SPANSION

Spanion's (NYSE: CODE) technology is at the heart of electronics systems, powering everything from the internet of today to the smart grid of tomorrow, positively impacting people's daily lives at work and play. Spanion's broad Flash memory product portfolio, smart innovation and industry leading service and support are enabling customers to achieve greater efficiency and success in their target markets. For more information, visit <http://www.spansion.com>.

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